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西新宿三井ビルディング

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お客様各位

日本テキサス・インスツルメンツ株式会社
営業・技術本部 カスタマドキュメント
マネージャ 牧 達郎 

SOT/SSOP/MSOP/SOIC パッケージ 一部製品 組立検査サイト追加のご案内
(一部製品対象除外の連絡)

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平素は弊社製品のご愛顧を賜り、厚くお礼申し上げます。さて、標題の件につきましてご連絡させていただきます。ご査収の程、宜しくお願い申し上げます。

タイにおける大洪水の影響により、HANA 社(タイ)サイトを含む数カ所の弊社協力工場における生産が、暫定的に被害を受けております。

TI は、連日、生産/流通拠点パートナーからの状況連絡を受けながら、供給面での致命的影響を緩和する為に、代替製造工場の選定及び認定を含む様々な施策を行っております。

今回のお知らせは、代替組立検査工場追加の連絡になります。お客様への供給停滞を最小限にとどめる為に、本通知内で明記したパッケージ製品について、既に認定されている工場への生産移管に向け早急に対応いたしております。

TI は、現行最善の情報/知識に基づき生産移管に必要な全てを本通知に盛り込むべく全ての方策を行っていますが、変更があった場合にも同様に本通知の更新版にて連絡いたします。さらに、選定された代替工場をより効率的に利用できると判断した時点で、これらに関連する供給移管に伴う PCN を発行する場合があります。

TI は、各生産拠点での認定状況を基に生産拠点選定及びパッケージ認定試験による前述の移管施策に加え、お客様への製品納入に先立ち、選別工程での歩留まり/選別分類比較評価を行う事でお客様での懸念事項の払拭に向け進めてまいります。また、供給の遅れを最小限にとどめると共に、品質を伴った製品の供給に努めてまいります。

次ページに詳細を掲載いたしました。お客様におかれましては、本通知発行日より **21 日以内**に、本通知受領のご確認をお願いいたします。供給遅延を最小限にとどめるために、TI は部材供給可能な代替工場での生産出荷が開始されるべくすでに施策の実施を開始いたしております。

本通知は、通知日前 24 ヶ月以内に本変更対象製品をご購入いただいたお客様に連絡させていただいております。

ご不明な点、ご質問等がございましたら、担当営業あるいは pcn_tij@list.ti.com にお問い合わせ下さい。

以上

変更概要

通知タイプ	☐ Initial notice (Plan)	☒ Final notice		
変更概要	Design/Specification	☐ Design	☐ Electrical	☐ Mechanical
	Wafer Fab	☐ Site	☐ Process	☐ Material
	Wafer Bump	☐ Site	☐ Process	☐ Material
	☒ Assembly	☒ Site	☐ Process	☒ Material
	☒ Test	☒ Site	☐ Process	
	☒ Others	☒ Packing/Shipping/Labeling ☐ -		
変更内容	下記変更について一部製品対象除外の連絡になります。 SOT/SSOP/MSOP/SOIC パッケージ 一部製品 組立検査サイト追加 現行 : HANA 社(タイ) 変更後 : HANA 社(タイ), UTAC2 社(タイ), NFME 社(中国), ASE 社(上海), ASE 社(威海)			
対象製品	対象製品リスト参照			
変更時期	—			
品質認定試験	☐ 計画	☒ 終了		
製品表示	☐ 変更無し	☒ 変更あり		
備考	—			

変更内容

内容 : 今回のお知らせは、下記変更について一部製品対象除外の連絡になります。TI-Hi ji (日本) サイト閉鎖に伴って2013年に製造終了する一部製品を変更対象から除外します。下記対象製品リストを参照下さい。

SOT/SSOP/MSOP/SOICパッケージ 一部製品の組立検査サイトについて、現行 HANA社(タイ)サイトにて製造していますが、HANA社(タイ)サイト一時的閉鎖による供給能力確保の為に、これに加えて、UTAC2社(タイ), NFME社(中国), ASE社(上海, 中国), ASE社(威海, 中国)サイトを追加します。組立部材、検査サイトについては下記の通り変更されます。下表を参照下さい。尚、今回の変更で、製品についての互換性(寸法/公差), 外観, 動作特性, 品質, 信頼性への影響はありません。

変更内容	現行	変更後
組立検査サイト	HANA社(タイ)	HANA社(タイ)
		UTAC2社(タイ)
		NFME社(中国)
		ASE社(上海, 中国)
		ASE社(威海, 中国)

理由 : HANA 社(タイ)サイト一時的閉鎖による供給能力確保の為

詳細：

PKG	参照 Qual#	組立 サイト	モールド樹脂	チップ接着剤	Au ボンディングワイヤ (径, 部材)
DBV	#1	HNT	R-13	PZ0013	0.6, 1.0 mil, Au
		NFME	R-13	A-03	0.8, 1.0 mil, Au
DCK	#2	HNT	R-13	A-09, PZ0013	0.6, 0.8, 1.0 mil, Au
		NFME	R-07	A-03, A-09	0.8, 1.0 mil, Au
DCY	#3	HNT	R-13	PZ0013, A-09, 400159	1.0, 1.5, 2.0 mil, Au
		NFME	R-07, R-17	A-06, A-09	1.0, 2.0 mil, Au
DBZ	#6	HNT	R-13	PZ-0013	1.0 mil, Au
		NS2	R-13	A-09	1.0 mil, Au
DBV	#4	HNT	R-13	PZ0013	0.6, 1.0 mil, Au
		NS2	R-13	A-09, PZ0013, PZ0001, PZ0017	0.6, 1.0 mil, Au
DCK	#5	HNT	R-13	A-09, PZ0013	1.0 mil, Au
		NS2	R-13	A-09, PZ0001	1.0 mil, Au
DDC	#8	HNT	R-13	400151	1.0 mil, Au
		NS2	R-13	PZ0013	1.0 mil, Au
DCN	#7	HNT	R-13	A-09, PZ0013	1.0 mil, Au
		NS2	R-13	A-09, PZ001	1.0 mil, Au
DGK	#12	HNT	R-13, EN2000601	PZ0013	1.0 mil, Au
		NS2	R-13	PZ0013	0.8, 1.0, 1.3 mil, Au
DGN	#12	HNT	R-13	PZ0013	1.0, 1.25 mil, Au
		NS2	R13	PZ0013	0.8, 1.0, 1.3, 2.0 mil, Au
DGQ	#12	HNT	R-13	PZ0013	1.0, 1.25 mil, Au
		NS2	R-13	PZ0013	0.8, 1.0, 1.3, 2.0 mil, Au
DGS	#12	HNT	R-13	PZ0013	1.0 mil, Au
		NS2	R-13	PZ0013	0.8, 1.0, 1.3, 2.0 mil, Au
DBZ	#11	HNT	R-13	PZ0013	1.0 mil, Au
		ASEWH	R-13	1120999A1	1.0 mil, Au
DBV	#9	HNT	R-13	PZ0013	0.6, 1.0 mil, Au
		ASEWH	R-13	C990J#316	0.8, 1.0 mil, Au
DCK	#10	HNT	R-13	A-09	0.8, 1.0 mil, Au
		ASEWH	R-13	1120999A1	0.8, 1.0 mil, Au
DDA	#13	HNT	R-13	400159	1.0, 1.3, 2.0 mil, Au
		ASESH	EN2000509	EY100063	1.0, 1.2, 2.0 mil, Cu 1.0, 1.2, 1.3, 2.0 mil, Au
DGK	#14	HNT	R-13, EN2000631	PZ0013, 400018	1.0 mil, Au
		ASESH	EN2000515, EN2000631	EY100063	1.0, 1.2, 1.3, 1.5, 2.0 mil, Au
DGN	#14	HNT	R-13	PZ0013	1.0, 1.2, 1.3, 1.5, 2.0 mil, Au
		ASESH	EN2000515	EY100063	1.0, 1.2, 1.3, 1.5, 2.0 mil, Au
DGQ	#14	HNT	R-13	PZ0013	1.0, 1.25 mil, Au
		ASESH	EN2000515	EY100063	1.0, 1.2, 1.3, 1.5, 2.0 mil, Au
DGS	#14	HNT	R-13	PZ0013	1.0, 1.2, 1.3, 1.5, 2.0 mil, Au
		ASESH	EN2000515, EN2000631	EY100063	1.0, 1.2, 1.3, 1.5, 2.0 mil, Au

The Leadframe finish for all devices at ASES will be NiPdAuAg, at HNT they are all NiPdAu.

表 1 変更組立部材

	追加検査サイト							
Package	NFME	NS2	ASEWH	ASESH	TIM	TAI	LEN	CRS
DBV	✓	☐	✓	☐	☐	☐	☐	✓
DBZ	☐	✓	☐	☐	☐	☐	☐	☐
DCK	✓	✓	✓	☐	☐	☐	✓	✓
DCN	☐	✓	☐	☐	☐	☐	☐	✓
DCY	✓	☐	☐	☐	☐	☐	☐	☐
DDA	☐	☐	☐	✓	✓	☐	☐	☐
DDC	☐	✓	☐	☐	☐	☐	☐	☐
DGK	☐	☐	☐	✓	✓	✓	☐	☐
DGN	☐	☐	☐	✓	✓	✓	☐	☐
DGQ	☐	✓	☐	☐	✓	☐	✓	☐
DGS	☐	☐	☐	✓	✓	✓	☐	☐

表2 追加検査サイト

備考：

HNT: HANA 社(タイ)
 NFME: NFME 社(中国)
 NS2: UTAC2 社(タイ)
 ASEWH: ASE 社(威海, 中国)
 ASESH: ASE 社(上海, 中国)
 TIM: TI-Malaysia(マレーシア)
 TAI: TI-Taiwan(台湾)
 LEN: Lingsen 社(台湾)
 CRS: CARSEM-S 社(CRS, マレーシア)

日本テキサス・インスツルメンツ株式会社

対象製品リスト

対象製品名 / 追加認定組立サイト: NFME

□: 既報対象品

74AUC1G126DBVRE4	INA212AIDCKT	SN74AUP1G07DBVRG4	SN74LVC1G58DBVRG4	TPS79718DCKRG4
74AUC1G126DBVRG4	INA212AIDCKTG4	SN74AUP1G08DBVR	SN74LVC2G06DBVR	TPS79730DCKR
74AUC1G240DBVRE4	INA213AIDCKR	SN74AUP1G08DBVRE4	SN74LVC2G06DBVRE4	TPS79730DCKRG4
74AUC1G240DBVRG4	INA213AIDCKRG4	SN74AUP1G08DBVRG4	SN74LVC2G06DBVRG4	TPS79733DCKR
74AVCH1T45DBVRE4	INA214AIDCKR	SN74AUP1G58DCKRG4	SN74LVC2G06DCKRG4	TPS79733DCKRG4
74AVCH1T45DBVRG4	INA214AIDCKRG4	SN74AUP1G80DBVT	TLV1117LV15DCYR	TS12A4516DBVR
74AVCH1T45DBVTE4	LMV981IDCKRG4	SN74AUP1G80DBVTE4	TLV1117LV25DCYR	TS12A4517DBVR
74AVCH1T45DBVTG4	OPA140AIDBVR	SN74AUP1G80DBVTG4	TLV70220PDBVR	TS321IDBVR
74AVCH1T45DCKRG4	OPA140AIDBVT	SN74AUP1G97DBVR	TLV7211AIDCKR	TS321IDBVRE4
74AVCH1T45DCKTG4	OPA171AIDBVT	SN74AUP1G97DBVRE4	TLV7211AIDCKRG4	TS321IDBVRG4
74CB3T1G125DBVRE4	OPA322AIDBVR	SN74AUP1G97DBVRG4	TMP20AIDCKR	TS5A1066DBVR
74CB3T1G125DBVRG4	OPA376AIDBVR	SN74AUP1T57DBVR	TPD4S009DCKR	TS5A1066DBVRE4
74CBT1G125DBVRE4	OPA376AIDBVRG4	SN74AUP1T57DBVRE4	TPD4S009DCKRG4	TS5A1066DBVRG4
74CBT1G125DBVRG4	REG1117	SN74AUP1T57DBVRG4	TPL0401A-10DCKR	TS5A3157DBVR
74CBT1G384DBVRE4	REG1117/2K5	SN74AUP1T57DCKRG4	TPL0401B-10DCKR	TS5A3157DBVRE4
74CBT1G384DBVRG4	REG1117/2K5G4	SN74AUP1T58DCKRG4	TPS3800G27DCKR	TS5A3157DBVRG4
74CBTD1G125DBVRE4	REG1117-5/2K5	SN74AUP1T97DBVT	TPS3800G27DCKRG4	TS5A3160DBVR
74CBTD1G125DBVRG4	REG1117-5/2K5G4	SN74AUP1T97DBVTE4	TPS3801-01DCKR	TS5A3160DBVRE4
74CBTD1G384DBVRE4	REG1117A/2K5	SN74AUP1T97DBVTG4	TPS3801-01DCKRG4	TS5A3160DBVRG4
74CBTD1G384DBVRG4	REG1117A/2K5G4	SN74AUP1T97DCKRG4	TPS3801E18DCKR	TS5A3160DCKJ
74LVC1G132DBVRE4	REG1117G4	SN74AVC1T45DBVR	TPS3801E18DCKRG4	TS5A3160DCKR
74LVC1G132DBVRG4	SN0710019DCKR	SN74AVC1T45DBVRE4	TPS3801K33DCKR	TS5A3160DCKRE4
74LVC1G132DCKRG4	SN1105002DCKR	SN74AVC1T45DBVRG4	TPS3801K33DCKRG4	TS5A3160DCKRG4
74LVC1G3208DBVRG4	SN200602108DCKR	SN74AVC1T45DCKRG4	TPS3801T50DCKR	TS5A3166DBVR
74LVC1G373DBVRE4	SN200602108DCKRG4	SN74AVCH1T45DBVR	TPS3801T50DCKRG4	TS5A3166DBVRE4
74LVC1GX04DCKRG4	SN74AUC1G00DBVR	SN74AVCH1T45DBVT	TPS3802K33DCKR	TS5A3166DBVRG4
HPA00328DCKR	SN74AUC1G00DBVRE4	SN74CB3T1G125DBVR	TPS3802K33DCKRG4	TS5A3167DBVR
HPA00366DCKR	SN74AUC1G00DBVRG4	SN74CBT1G125DBVR	TPS3802L30DCKR	TS5A3167DBVRE4
HPA00422DCKR	SN74AUC1G02DCKR	SN74CBT1G384DBVR	TPS3802L30DCKRG4	TS5A3167DBVRG4
HPA00423DCKR	SN74AUC1G02DCKRE4	SN74CBTD1G125DBVR	TPS3803-01DCKR	TS5A4594DBVR
HPA00456DCKR	SN74AUC1G02DCKRG4	SN74CBTD1G384DBVR	TPS3803-01DCKRG4	TS5A4594DBVRE4
HPA00528DCKR	SN74AUC1G07DBVR	SN74LVC1G0832DBVR	TPS3805H33DCKR	TS5A4594DBVRG4
HPA00579DCKR	SN74AUC1G07DBVRE4	SN74LVC1G132DBVR	TPS3805H33DCKRG4	TS5A4597DBVR
HPA00653DCKR	SN74AUC1G07DBVRG4	SN74LVC1G132DBVT	TPS71501DCKR	TS5A4597DBVRE4
HPA00681DCKR	SN74AUC1G126DBVR	SN74LVC1G132DBVTE4	TPS71501DCKR/2801	TS5A4597DBVRG4
HPA00683DCKR	SN74AUC1G14DBVR	SN74LVC1G132DBVTG4	TPS71501DCKRG4	TS5A4624DCKR
HPA00763DCKR	SN74AUC1G14DBVRE4	SN74LVC1G132DCKR	TPS71523DCKR	TS5A4624DCKRE4
HPA01091DBVR	SN74AUC1G14DBVRG4	SN74LVC1G18DBVR	TPS71523DCKRG4	TS5A4624DCKRG4
INA199A1DCKR	SN74AUC1G240DBVR	SN74LVC1G18DBVRE4	TPS71525DCKR	TS5A4624DCKT
INA199A2DCKR	SN74AUC1G32DBVR	SN74LVC1G18DBVRG4	TPS71525DCKRG4	TS5A4624DCKTE4
INA199A2DCKT	SN74AUC1G32DBVRE4	SN74LVC1G27DCKRG4	TPS71530DCKR	TS5A4624DCKTG4
INA199A3DCKR	SN74AUC1G32DBVRG4	SN74LVC1G3208DBVR	TPS71530DCKRG4	TXB0101DBVR
INA210A1DCKR	SN74AUC2G04DCKRG4	SN74LVC1G373DBVR	TPS71533DCKR	TXB0101DBVRG4
INA210A1DCKRG4	SN74AUC2G07DBVR	SN74LVC1G38DBVR	TPS71533DCKRG4	TXS0101DBVR
INA211A1DCKR	SN74AUC2G07DBVRE4	SN74LVC1G38DBVRE4	TPS71550DCKR	TXS0101DBVRG4
INA211A1DCKRG4	SN74AUC2G07DBVRG4	SN74LVC1G38DBVRG4	TPS71550DCKR/2801	
INA211A1DCKT	SN74AUP1G07DBVR	SN74LVC1G58DBVR	TPS71550DCKRG4	
INA211A1DCKTG4	SN74AUP1G07DBVRE4	SN74LVC1G58DBVRE4	TPS79718DCKR	

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対象製品名 / 追加認定組立サイト: UTAC2 取消線: 対象除外品 □: 既報対象品				
74AUC1G126DBVRE4	SN65HVD3085EDGKR	THS4502CDGN	TPA321DGNRG4	TPS62054DGS64
74AUC1G126DBVRG4	SN65HVD3085EDGKRG4	THS4502CDGNG4	TPA6100A2DGKR	TPS62054DGSR
74AUC1G240DBVRE4	SN65HVD3088EDGK	THS4502IDGN	TPA6100A2DGKRG4	TPS62054DGSRG4
74AUC1G240DBVRG4	SN65HVD3088EDGKG4	THS4502IDGNG4	TPA6110A2DGNR	TPS62056DGS
74AVCH1T45DBVRE4	SN65HVD3088EDGKR	THS4502IDGNR	TPA6110A2DGNRG4	TPS62056DGS64
74AVCH1T45DBVRG4	SN65HVD3088EDGKRG4	THS4502IDGNRG4	TPA701DGN	TPS62056DGSR
74AVCH1T45DBVTE4	SN65HVD485EDGKR	THS4503CDGNR	TPA701DGNRG4	TPS62056DGSRG4
74AVCH1T45DBVTG4	SN65HVD485EDGKRG4	THS4503CDGNGRG4	TPA701DGNR	TPS62120DCNR
74AVCH1T45DCKRG4	SN65LVD176DGK	THS4503IDGNR	TPA701DGNRG4	TPS62120DCNT
74AVCH1T45DCKTG4	SN65LVD176DGKG4	THS4503IDGNRG4	TPA711DGN	TPS62220DDCR
74CB3T1G125DBVRE4	SN65LVD176DGKR	THS4505DGN	TPA711DGNRG4	TPS62220DDCRG4
74CB3T1G125DBVRG4	SN65LVD176DGKRG4	THS4505DGNRG4	TPA711DGNR	TPS62220DDCT
74CBT1G125DBVRE4	SN65LVD176DGK	THS4505DGNR	TPA711DGNRG4	TPS62220DDCTG4
74CBT1G125DBVRG4	SN65LVD176DGKG4	THS4505DGNRG4	TPA721DGNR	TPS62221DDCR
74CBT1G384DBVRE4	SN65LVD176DGKR	THS4631DGN	TPA721DGNRG4	TPS62221DDCRG4
74CBT1G384DBVRG4	SN65LVD176DGKRG4	THS4631DGNRG4	TPA731DGN	TPS62221DDCT
74CBTD1G125DBVRE4	SN65LVD176DGK	THS4631DGNR	TPA731DGNRG4	TPS62221DDCTG4
74CBTD1G125DBVRG4	SN65LVD176DGKG4	THS4631DGNRG4	TPA731DGNR	TPS62222DDCR
74CBTD1G384DBVRE4	SN65LVD176DGKR	THS6072IDGNR	TPA731DGNRG4	TPS62222DDCRG4
74CBTD1G384DBVRG4	SN65LVD176DGKRG4	THS6072IDGNRG4	TPA741DGNR	TPS62222DDCT
74LVC1G132DBVRE4	SN65LVD176DGK	TLC0711DGNR	TPA741DGNRG4	TPS62222DDCTG4
74LVC1G132DBVRG4	SN65LVD176DGKG4	TLC0711DGNRG4	TPD2E009DBZR	TPS62223DDCT
74LVC1G132DCKRG4	SN65LVD176DGKR	TLC072CDGNR	TPD4S009DCKR	TPS62223DDCTG4
74LVC1G3208DBVRG4	SN65LVD176DGKRG4	TLC072CDGNGRG4	TPD4S009DCKRG4	TPS62224DDCR
74LVC1G373DBVRE4	SN65LVD176DGK	TLC072IDGN	TPD4S009DGSR	TPS62224DDCRG4
74LVC1GX04DCKRG4	SN65LVD176DGKRG4	TLC072IDGNG4	TPL0401A-10DCKR	TPS62224DDCT
BQ24202DGN	SN74AUC1G00DBVR	TLC072IDGNR	TPL0401B-10DCKR	TPS62224DDCTG4
BQ24202DGNRG4	SN74AUC1G00DBVRE4	TLC072IDGNRG4	TPL0501-100DCNR	TPS62225DDCR
DAC75541DGS	SN74AUC1G00DBVRG4	TLC073CDGQ	TPS22960DCNR	TPS62227DDCR
DAC75541DGS64	SN74AUC1G02DCKR	TLC073CDGQG4	TPS3305-33DGNR	TPS62227DDCRG4
DAC75541DGSR	SN74AUC1G02DCKRE4	TLC073IDGQR	TPS3305-33DGNRG4	TPS62227DDCT
DAC75541DGSRG4	SN74AUC1G02DCKRG4	TLC073IDGQRG4	TPS3306-15DGKR	TPS62227DDCTG4
DAC85511ADGKR	SN74AUC1G07DBVR	TLC081CDGNR	TPS3306-15DGKRG4	TPS62228DDCR
DAC85511ADGKRG4	SN74AUC1G07DBVRE4	TLC081CDGNGRG4	TPS3306-18DGKR	TPS62228DDCRG4
DAC85511ADGKT	SN74AUC1G07DBVRG4	TLC081IDGNR	TPS3306-18DGKRG4	TPS62228DDCT
DAC85511ADGKTG4	SN74AUC1G126DBVR	TLC081IDGNRG4	TPS3307-18DGNR	TPS62228DDCTG4
DAC85511DGKR	SN74AUC1G14DBVR	TLC082IDGNR	TPS3307-18DGNRG4	TPS62229DDCT
DAC85511DGKRG4	SN74AUC1G14DBVRE4	TLC082IDGNRG4	TPS3617-50DGKR	TPS62229DDCTG4
DAC85511DGKT	SN74AUC1G14DBVRG4	TLC083IDGQ	TPS3617-50DGKRG4	TPS71501DCKR
DAC85511DGKTG4	SN74AUC1G240DBVR	TLC083IDGQG4	TPS3619-33DGKR	TPS71501DCKR/2801
DRV8830DGQR	SN74AUC1G32DBVR	TLV2242IDGK	TPS3619-33DGKRG4	TPS71501DCKRG4
DRV8832DGQR	SN74AUC1G32DBVRE4	TLV2242IDGKG4	TPS3620-33DGKR	TPS71523DCKR
HPA00107DDCR	SN74AUC1G32DBVRG4	TLV2242IDGKR	TPS3620-33DGKRG4	TPS71523DCKRG4
HPA00210DGSR	SN74AUC2G04DCKRG4	TLV2242IDGKRG4	TPS3620-33DGKT	TPS71525DCKR
HPA00245DGSR	SN74AUC2G07DBVR	TLV2373IDGSR	TPS3620-33DGKTG4	TPS71525DCKRG4
HPA00296DGSR	SN74AUC2G07DBVRE4	TLV2373IDGSRG4	TPS3705-33DGNR	TPS71530DCKR
HPA00305DDCR	SN74AUC2G07DBVRG4	TLV2402CDGK	TPS3705-33DGNRG4	TPS71530DCKRG4
HPA00328DCKR	SN74AUP1G07DBVR	TLV2402CDGKG4	TPS3707-30DGNR	TPS71533DCKR
HPA00366DCKR	SN74AUP1G07DBVRE4	TLV2402CDGKRG4	TPS3707-30DGNRG4	TPS71533DCKRG4
HPA00422DCKR	SN74AUP1G07DBVRG4	TLV2402CDGKRG4	TPS3707-33DGNR	TPS71550DCKR
HPA00423DCKR	SN74AUP1G08DBVR	TLV2402IDGKR	TPS3707-33DGNRG4	TPS71550DCKR/2801
HPA00456DCKR	SN74AUP1G08DBVRE4	TLV2402IDGKRG4	TPS3800G27DCKR	TPS71550DCKRG4
HPA00528DCKR	SN74AUP1G08DBVRG4	TLV2452CDGK	TPS3800G27DCKRG4	TPS77133DGKR

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HPA00579DCKR	SN74AUP1G58DCKRG4	TLV2452CDGKG4	TPS3801-01DCKR	TPS77133DGKRG4
HPA00653DCKR	SN74AUP1G80DBVT	TLV2452CDGKR	TPS3801-01DCKRG4	TPS77301DGKR
HPA00657DGNR	SN74AUP1G80DBVTE4	TLV2452CDGKRG4	TPS3801E18DCKR	TPS77301DGKRG4
HPA00681DCKR	SN74AUP1G80DBVTG4	TLV24521DGKR	TPS3801E18DCKRG4	TPS77401DGKR
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HPA00763DCKR	SN74AUP1G97DBVRE4	TLV2453CDGSR	TPS3801K33DCKRG4	TPS77901DGKR
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INA199A3DCKR	SN74AUP1T58DCKRG4	TLV24631DGS	TPS3802L30DCKRG4	TPS79433DGNR
INA210A1DCKR	SN74AUP1T97DBVT	TLV24631DGSG4	TPS3803-01DCKR	TPS79433DGNRG4
INA210A1DCKRG4	SN74AUP1T97DBVTE4	TLV24631DGSR	TPS3803-01DCKRG4	TPS79718DCKR
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INA211A1DCKRG4	SN74AUP1T97DCKRG4	TLV2472CDGSR	TPS3805H33DCKRG4	TPS79730DCKR
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INA214A1DCKR	SN74CB3T1G125DBVR	TLV26221DGKRG4	TPS60204DGS	TPS92510DGQ
INA214A1DCKRG4	SN74CBT1G125DBVR	TLV272CDGKR	TPS60204DGSG4	TPS92510DGQR
INA826A1DGK	SN74CBT1G384DBVR	TLV272CDGKRG4	TPS60204DGSR	TS12A12511DCNR
INA826A1DGKR	SN74CBTD1G125DBVR	TLV27621DGKR	TPS60204DGSRG4	TS12A4516DBVR
LMV3421DGKR	SN74CBTD1G384DBVR	TLV27621DGKRG4	TPS60205DGSR	TS12A4517DBVR
LMV3421DGKRG4	SN74LVC1G0832DBVR	TLV27701DGKR	TPS60205DGSRG4	TS3211DBVR
LMV9811DCKRG4	SN74LVC1G132DBVR	TLV27701DGKRG4	TPS60210DGS	TS3211DBVRE4
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LPV358DGKRG4	SN74LVC1G132DBVTE4	TLV2772CDGKRG4	TPS60210DGSR	TS3A24159DGSR
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OPA140A1DBVT	SN74LVC1G132DCKR	TLV2782CDGKG4	TPS60211DGS	TS3A4741DCNR
OPA140A1DGKR	SN74LVC1G18DBVR	TLV2782CDGKR	TPS60211DGSG4	TS3A4741DGKR
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OPA1641A1DGKR	SN74LVC1G38DBVR	TLV27L21DGKR	TPS60300DGSRG4	TS5A1066DBVR
OPA1641A1DGKT	SN74LVC1G38DBVRE4	TLV27L21DGKRG4	TPS60301DGSR	TS5A1066DBVRE4
OPA171A1DBVT	SN74LVC1G38DBVRG4	TLV3402CDGKR	TPS60301DGSRG4	TS5A1066DBVRG4
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OPA2140A1DGKR	SN74LVC1G58DBVRE4	TLV34021DGKR	TPS60302DGSG4	TS5A22362DGSRG4
OPA2188A1DGKR	SN74LVC1G58DBVRG4	TLV34021DGKRG4	TPS60303DGS	TS5A22364DGSR
OPA2188A1DGKT	SN74LVC2G06DBVR	TLV3702CDGKR	TPS60303DGSG4	TS5A22364DGSRG4
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OPA2320A1DGKR	SN74LVC2G06DBVRG4	TLV37021DGK	TPS60303DGSRG4	TS5A23157DGSR/2354
OPA2320A1DGKT	SN74LVC2G06DCKRG4	TLV37021DGKG4	TPS60311DGSR	TS5A23157DGSRE4
OPA2322A1DGKR	SN75HVD3082EDGKR	TLV41111DGNR	TPS60311DGSRG4	TS5A23157DGSRG4
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OPA2377A1DGKR	SN761663DGKR	TLV41121DGNR	TPS60312DGSR	TS5A23157DGSTE4
OPA2377A1DGKT	SN761663DGKRG4	TLV41121DGNRG4	TPS60312DGSRG4	TS5A23157DGSTG4
OPA2379A1DCNRG4	SN761666DGKR	TLV4113CDGQR	TPS60313DGS	TS5A23159DGSR
OPA322A1DBVR	SN761666DGKRG4	TLV4113CDGQGR4	TPS60313DGSG4	TS5A23159DGSRE4
OPA376A1DBVR	SNHVD3082EDGKG4	TLV70012DDCR	TPS60500DGS	TS5A23159DGSRG4

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PCA9517DGKR	TCA4311DGKR	TLV7211A1DCKR	TPS60500DGSRG4	TS5A23160DGSRG4
PCA9517DGKRG4	TCA4311DGKRG4	TLV7211A1DCKRG4	TPS60501DGS	TS5A3157DBVR
PCA9536DGKR	THS30011DGNR	TMP20A1DCKR	TPS60501DGSRG4	TS5A3157DBVRE4
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REF50101DGKR	THS3120CDGNR	TMP431DDGKT	TPS60502DGSRG4	TS5A3160DBVRG4
REF50101DGKT	THS3120CDGNRG4	TMP432ADGSR	TPS61000DGS	TS5A3160DCKJ
REF5025A1DGKR	THS3202DGN	TMP432ADGST	TPS61000DGS4	TS5A3160DCKR
REF5025A1DGKT	THS3202DNG4	TMP432BDGSR	TPS61002DGS	TS5A3160DCKRE4
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REF50251DGKT	THS3202DGNRG4	TMP435ADGSR	TPS61004DGS	TS5A3166DBVR
REF5030A1DGKR	THS4011CDGN	TMP435ADGST	TPS61004DGS4	TS5A3166DBVRE4
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REF50301DGKT	THS40221DNG4	TPA0211DGNR	TPS61005DGS	TS5A3167DBVRE4
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REF50401DGKR	THS4121CDGKR	TPA0213DGQRG4	TPS61006DGS4	TS5A4594DBVRE4
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REF5045A1DGKT	THS41211DGKRG4	TPA0233DGQR	TPS61010DGS	TS5A4597DBVRE4
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REF50451DGKT	THS41211DGNRG4	TPA0253DGQ	TPS62000DGS	TS5A4624DCKR
REF5050A1DGKR	THS4130CDGNR	TPA0253DGQG4	TPS62000DGSRG4	TS5A4624DCKRE4
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REF50501DGKT	THS41401DNG4	TPA301DGN	TPS62007DGS	TS5A4624DCKTE4
SN0710019DCKR	THS4151CDGK	TPA301DNG4	TPS62007DGSRG4	TS5A4624DCKTG4
SN1105002DCKR	THS4151CDGKG4	TPA301DGNR	TPS62051DGS	TXB0101DBVR
SN200602108DCKR	THS4211DGK	TPA301DGNRG4	TPS62051DGS4	TXB0101DBVRG4
SN200602108DCKRG4	THS4211DGKG4	TPA311DGN	TPS62051DGS	TXS0101DBVR
SN65EPT21DGKR	THS45001DGK	TPA311DNG4	TPS62051DGSRG4	TXS0101DBVRG4
SN65EPT23DGKR	THS45001DGKG4	TPA311DGNR	TPS62052DGS	
SN65HVD3082EDGK	THS45001DGNR	TPA311DGNRG4	TPS62052DGSRG4	
SN65HVD3082EDGKR	THS45001DGNRG4	TPA321DGNR	TPS62054DGS	

対象製品名 / 追加認定組立サイト: ASE-Shanghai				
取消線: 対象除外品 ☐ :Non-Cu 線製品 ☐ :既報対象品				
BQ24202DGN	SN65LVDM176DGK	TLC0811DGNR	TPA311DGN	TPS60311DGSRG4
BQ24202DNG4	SN65LVDM176DGKG4	TLC0811DGNRG4	TPA311DNG4	TPS60312DGS
DAC75541DGS	SN65LVDM176DGKR	TLC0821DGNR	TPA311DGNR	TPS60312DGS
DAC75541DGS4	SN65LVDM176DGKRG4	TLC0821DGNRG4	TPA311DGNRG4	TPS60312DGSRG4
DAC75541DGS	SN65LVDS100DGK	TLC0831DGQ	TPA321DGNR	TPS60313DGS
DAC75541DGSRG4	SN65LVDS100DGKG4	TLC0831DGQG4	TPA321DGNRG4	TPS60313DGS4
DAC85511ADGKR	SN65LVDS100DGKR	TLV22421DGK	TPA6100A2DGKR	TPS60500DGS
DAC85511ADGKRG4	SN65LVDS100DGKRG4	TLV22421DGKG4	TPA6100A2DGKRG4	TPS60500DGS4
DAC85511ADGKT	SN65LVDS179DGK	TLV22421DGKR	TPA6110A2DGNR	TPS60500DGS
DAC85511ADGKTG4	SN65LVDS179DGKG4	TLV22421DGKRG4	TPA6110A2DGNRG4	TPS60500DGSRG4
DAC85511DGKR	SN65LVDS179DGKR	TLV23731DGS	TPA701DGN	TPS60501DGS
DAC85511DGKRG4	SN65LVDS179DGKRG4	TLV23731DGSRG4	TPA701DNG4	TPS60501DGSRG4
DAC85511DGKT	SN65LVDS9637DGKR	TLV2402CDGK	TPA701DGNR	TPS60502DGS
DAC85511DGKTG4	SN65LVDS9637DGKRG4	TLV2402CDGKG4	TPA701DGNRG4	TPS60502DGS4
DRV8830DGQR	SN65LVDS9638DGKR	TLV2402CDGKR	TPA711DGN	TPS60502DGS

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DRV8832DGQR	SN65LVDS9638DGKRG4	TLV2402CDGKRG4	TPA711DGN4	TPS60502DGSRG4
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HPA00231DDA	SN65LVD101DGKR	TLV2452CDGK	TPA721DGNR	TPS61002DGSR
HPA00231DDAR	SN65LVD101DGKRG4	TLV2452CDGKRG4	TPA721DGNRG4	TPS61002DGSRG4
HPA00245DGSR	SN65LVEL11DGKR	TLV2452CDGKR	TPA731DGN	TPS61004DGS
HPA00295DDAR	SN65LVELT23DGKR	TLV2452CDGKRG4	TPA731DGN4	TPS61004DGSRG4
HPA00296DGSR	SN75HVD3082EDGKR	TLV2452IDGKR	TPA731DGNR	TPS61005DGS
HPA00393DDAR	SN75HVD3082EDGKRG4	TLV2452IDGKRG4	TPA731DGNRG4	TPS61005DGSRG4
HPA00657DGNR	SN761663DGKR	TLV2453CDGSR	TPA741DGNR	TPS61005DGSR
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INA826A1DGK	SN761666DGKR	TLV2453IDGSR	TPD4S009DGSR	TPS61006DGS
INA826A1DGKR	SN761666DGKRG4	TLV2453IDSGRG4	TPS2376DDAR-H	TPS61006DGSRG4
LMV342IDGKR	SNHVD3082EDGKRG4	TLV2463CDGSR	TPS2376DDAR-HG4	TPS61007DGS
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REF5010IDGKT	THS4502IDGN	TLV4111IDGNRG4	TPS60200DGSR	TPS92510DGQ
REF5025A1DGKR	THS4502IDNG4	TLV4112IDGNR	TPS60200DGSRG4	TPS92510DGQR

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REF5025A1DGKT	THS45021DGNR	TLV41121DGNRG4	TPS60201DGS	TS3A24159DGSR
REF50251DGKR	THS45021DGNRG4	TLV4113CDGQR	TPS60201DGS64	TS3A24159DGSRG4
REF50251DGKT	THS4503CDGNR	TLV4113CDGQRG4	TPS60203DGS	TS3A4741DGKR
REF5030A1DGKR	THS4503CDGNRG4	TMP431CDGKR	TPS60203DGS64	TS3A4741DGKRG4
REF5030A1DGKT	THS45031DGNR	TMP431CDGKT	TPS60204DGS	TS3A4742DGKR
REF50301DGKR	THS45031DGNRG4	TMP431DDGKR	TPS60204DGS64	TS3A4742DGKRG4
REF50301DGKT	THS4505DGN	TMP431DDGKT	TPS60204DGSR	TS3USB30EDGSR
REF5040A1DGKR	THS4505DGN64	TMP432ADGSR	TPS60204DGSRG4	TS5A22362DGSR
REF5040A1DGKT	THS4505DGNR	TMP432ADGST	TPS60205DGSR	TS5A22362DGSRG4
REF50401DGKR	THS4505DGNRG4	TMP432BDGSR	TPS60205DGSRG4	TS5A22364DGSR
REF50401DGKT	THS4631DGN	TMP432BDGST	TPS60210DGS	TS5A22364DGSRG4
REF5045A1DGKR	THS4631DGN64	TMP435ADGSR	TPS60210DGS64	TS5A23157DGSR
REF5045A1DGKT	THS4631DGNR	TMP435ADGST	TPS60210DGSR	TS5A23157DGSR/2354
REF50451DGKR	THS4631DGNRG4	TPA0211DGN	TPS60210DGSRG4	TS5A23157DGSRE4
REF50451DGKT	THS60721DGNR	TPA0211DGN64	TPS60211DGS	TS5A23157DGSRG4
REF5050A1DGKR	THS60721DGNRG4	TPA0211DGNR	TPS60211DGS64	TS5A23157DGST
REF5050A1DGKT	TL96001DGKR-P	TPA0211DGNRG4	TPS60212DGSR	TS5A23157DGSSTE4
REF50501DGKR	TLC0711DGNR	TPA0213DGQR	TPS60212DGSRG4	TS5A23157DGS TG4
REF50501DGKT	TLC0711DGNRG4	TPA0213DGQRG4	TPS60300DGS	TS5A23159DGSR
SN65EPT21DGKR	TLC072CDGNR	TPA0223DGQR	TPS60300DGS64	TS5A23159DGSRE4
SN65EPT23DGKR	TLC072CDGNRG4	TPA0223DGQRG4	TPS60300DGSR	TS5A23159DGSRG4
SN65HVD3082EDGK	TLC0721DGN	TPA0233DGQR	TPS60300DGSRG4	TS5A23160DGSR
SN65HVD3082EDGKR	TLC0721DGN64	TPA0233DGQRG4	TPS60301DGSR	TS5A23160DGSRE4
SN65HVD3085EDGKR	TLC0721DGNR	TPA0253DGQ	TPS60301DGSRG4	TS5A23160DGSRG4
SN65HVD3085EDGKRG4	TLC0721DGNRG4	TPA0253DGQG4	TPS60302DGS	UCC27200DDA
SN65HVD3088EDGK	TLC073CDGQ	TPA0253DGQR	TPS60302DGS64	UCC27200DDAG4
SN65HVD3088EDGK64	TLC073CDGQG4	TPA0253DGQRG4	TPS60303DGS	UCC27200DDAR
SN65HVD3088EDGKR	TLC0731DGQR	TPA301DGN	TPS60303DGS64	UCC27200DDARG4
SN65HVD3088EDGKRG4	TLC0731DGQRG4	TPA301DGN64	TPS60303DGSR	UCC27201ADDAR
SN65HVD485EDGKR	TLC081CDGNR	TPA301DGNR	TPS60303DGSRG4	
SN65HVD485EDGKRG4	TLC081CDGNRG4	TPA301DGNRG4	TPS60311DGSR	

対象製品名 / 追加認定組立サイト: ASE-Weihai □: 既報対象品				
74AUC1G126DBVRE4	INA211A1DCKT	SN74AUP1G80DBVTE4	SN74LVC2G06DCKRG4	TPS79733DCKR
74AUC1G126DBVRG4	INA211A1DCKTG4	SN74AUP1G80DBVTG4	TLV70220PDBVR	TPS79733DCKRG4
74AUC1G240DBVRE4	INA212A1DCKT	SN74AUP1G97DBVR	TLV7211A1DCKR	TS12A4516DBVR
74AUC1G240DBVRG4	INA212A1DCKTG4	SN74AUP1G97DBVRE4	TLV7211A1DCKRG4	TS12A4517DBVR
74AVCH1T45DBVRE4	INA214A1DCKR	SN74AUP1G97DBVRG4	TMP20A1DCKR	TS3211DBVR
74AVCH1T45DBVRG4	INA214A1DCKRG4	SN74AUP1T57DBVR	TPD2E009DBZR	TS3211DBVRE4
74AVCH1T45DBVTE4	LMV9811DCKRG4	SN74AUP1T57DBVRE4	TPD4S009DCKR	TS3211DBVRG4
74AVCH1T45DBVTG4	OPA140A1DBVR	SN74AUP1T57DBVRG4	TPD4S009DCKRG4	TS5A1066DBVR
74AVCH1T45DCKRG4	OPA140A1DBVT	SN74AUP1T57DCKRG4	TPL0401A-10DCKR	TS5A1066DBVRE4
74AVCH1T45DCKTG4	OPA171A1DBVT	SN74AUP1T58DCKRG4	TPL0401B-10DCKR	TS5A1066DBVRG4
74CB3T1G125DBVRE4	OPA322A1DBVR	SN74AUP1T97DBVT	TPS3800G27DCKR	TS5A3157DBVR
74CB3T1G125DBVRG4	OPA376A1DBVR	SN74AUP1T97DBVTE4	TPS3800G27DCKRG4	TS5A3157DBVRE4
74CBT1G125DBVRE4	OPA376A1DBVRG4	SN74AUP1T97DBVTG4	TPS3801-01DCKR	TS5A3157DBVRG4
74CBT1G125DBVRG4	SN0710019DCKR	SN74AUP1T97DCKRG4	TPS3801-01DCKRG4	TS5A3160DBVR
74CBT1G384DBVRE4	SN1105002DCKR	SN74AVC1T45DBVR	TPS3801E18DCKR	TS5A3160DBVRE4
74CBT1G384DBVRG4	SN200602108DCKR	SN74AVC1T45DBVRE4	TPS3801E18DCKRG4	TS5A3160DBVRG4
74CBTD1G125DBVRE4	SN200602108DCKRG4	SN74AVC1T45DBVRG4	TPS3801K33DCKR	TS5A3160DCKJ
74CBTD1G125DBVRG4	SN74AUC1G00DBVR	SN74AVC1T45DCKRG4	TPS3801K33DCKRG4	TS5A3160DCKR
74CBTD1G384DBVRE4	SN74AUC1G00DBVRE4	SN74AVCH1T45DBVR	TPS3801T50DCKR	TS5A3160DCKRE4
74CBTD1G384DBVRG4	SN74AUC1G00DBVRG4	SN74AVCH1T45DBVT	TPS3801T50DCKRG4	TS5A3160DCKRG4
74LVC1G132DBVRE4	SN74AUC1G02DCKR	SN74CB3T1G125DBVR	TPS3802K33DCKR	TS5A3166DBVR
74LVC1G132DBVRG4	SN74AUC1G02DCKRE4	SN74CBT1G125DBVR	TPS3802K33DCKRG4	TS5A3166DBVRE4

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74LVC1G132DCKRG4	SN74AUC1G02DCKRG4	SN74CBT1G384DBVR	TPS3802L30DCKR	TS5A3166DBVRG4
74LVC1G3208DBVRG4	SN74AUC1G07DBVR	SN74CBTD1G125DBVR	TPS3802L30DCKRG4	TS5A3167DBVR
74LVC1G373DBVRE4	SN74AUC1G07DBVRE4	SN74CBTD1G384DBVR	TPS3803-01DCKR	TS5A3167DBVRE4
74LVC1G04DCKRG4	SN74AUC1G07DBVRG4	SN74LVC1G0832DBVR	TPS3803-01DCKRG4	TS5A3167DBVRG4
HPA00328DCKR	SN74AUC1G126DBVR	SN74LVC1G132DBVR	TPS3805H33DCKR	TS5A4594DBVR
HPA00366DCKR	SN74AUC1G14DBVR	SN74LVC1G132DBVT	TPS3805H33DCKRG4	TS5A4594DBVRE4
HPA00422DCKR	SN74AUC1G14DBVRE4	SN74LVC1G132DBVTE4	TPS71501DCKR	TS5A4594DBVRG4
HPA00423DCKR	SN74AUC1G14DBVRG4	SN74LVC1G132DBVTG4	TPS71501DCKR/2801	TS5A4597DBVR
HPA00456DCKR	SN74AUC1G240DBVR	SN74LVC1G132DCKR	TPS71501DCKRG4	TS5A4597DBVRE4
HPA00528DCKR	SN74AUC1G32DBVR	SN74LVC1G18DBVR	TPS71523DCKR	TS5A4597DBVRG4
HPA00579DCKR	SN74AUC1G32DBVRE4	SN74LVC1G18DBVRE4	TPS71523DCKRG4	TS5A4624DCKR
HPA00653DCKR	SN74AUC1G32DBVRG4	SN74LVC1G18DBVRG4	TPS71525DCKR	TS5A4624DCKRE4
HPA00681DCKR	SN74AUC2G04DCKRG4	SN74LVC1G27DCKRG4	TPS71525DCKRG4	TS5A4624DCKRG4
HPA00683DCKR	SN74AUC2G07DBVR	SN74LVC1G3208DBVR	TPS71530DCKR	TS5A4624DCKT
HPA00763DCKR	SN74AUC2G07DBVRE4	SN74LVC1G373DBVR	TPS71530DCKRG4	TS5A4624DCKTE4
HPA01091DBVR	SN74AUC2G07DBVRG4	SN74LVC1G38DBVR	TPS71533DCKR	TS5A4624DCKTG4
INA199A1DCKR	SN74AUP1G07DBVR	SN74LVC1G38DBVRE4	TPS71533DCKRG4	TXB0101DBVR
INA199A2DCKR	SN74AUP1G07DBVRE4	SN74LVC1G38DBVRG4	TPS71550DCKR	TXB0101DBVRG4
INA199A2DCKT	SN74AUP1G07DBVRG4	SN74LVC1G58DBVR	TPS71550DCKR/2801	TXS0101DBVR
INA199A3DCKR	SN74AUP1G08DBVR	SN74LVC1G58DBVRE4	TPS71550DCKRG4	TXS0101DBVRG4
INA210A1DCKR	SN74AUP1G08DBVRE4	SN74LVC1G58DBVRG4	TPS79718DCKR	
INA210A1DCKRG4	SN74AUP1G08DBVRG4	SN74LVC2G06DBVR	TPS79718DCKRG4	
INA211A1DCKR	SN74AUP1G58DCKRG4	SN74LVC2G06DBVRE4	TPS79730DCKR	
INA211A1DCKRG4	SN74AUP1G80DBVT	SN74LVC2G06DBVRG4	TPS79730DCKRG4	

製品表示

今回の変更に伴い、出荷ラベルに記載の原産地(ラベル箇所:22L)及び製品捺印が下記のようになります。

	組立サイト	組立サイトコード(22L)
現行	Hana-Thai	ASO: HNT
追加認定	UTAC2	ASO: NS2
	NFME	ASO: NFM
	ASE-Shanghai	ASO: ASH
	ASE-Weihai	ASO: AWH



図1 出荷ラベルの例

信頼性試験

Reference Qual #1

信頼性試験結果				
信頼性試験期間	開始	—	終了	2011 年 8 月 8 日
信頼性試験 - 試料構成詳細				
Qual Device:	TPS73201QDBVRQ1	-	-	
Assembly Site:	NFME	Package/Code/Pins:	SOT/DBV/5	
Mount Compound:	A-03	Mold Compound:	R-13	
Bond Wire:	1.0 mil Dia., Au	Leadframe (Finish, Base):	NiPdAu, Cu	
MSL:	JEDEC L-1/260C	-	-	
信頼性試験結果				
Reliability Test	Condition / Duration	Sample Size/ Fails		
		Lot #1	Lot #2	Lot #3
**HTOL	125C/1000hrs, 150C/408hrs	77/0	77/0	77/0
**HAST	85C/85%, 1000 hrs	77/0	77/0	77/0
**Autoclave	121C, 96 Hrs	77/0	77/0	77/0
**T/C	-65C/150C, 500 Cyc	77/0	77/0	77/0
Surface Mount Solderability	Pb Solder	22/0	-	-
Physical Dimensions	per mechanical drawing	10/0	10/0	10/0
Moisture Sensitivity	JEDEC L-1/260C	12/0	-	-
Note: ** Preconditioning sequence: JEDEC L-1/260C				

信頼性試験結果				
信頼性試験期間	開始	—	終了	2010 年 9 月 17 日
信頼性試験 - 試料構成詳細				
ID:	Device1	Device2		
Qual Device:	TPS2065DBV	TPS61041DBV		
Assembly Site:	NFME	NFME		
Package/Code/Pins:	SOT/DBV/5	SOT/DBV/5		
Mount Compound:	A-03	A-03		
Mold Compound:	R-13	R-13		
Bond Wire:	0.8 mil Dia., Au	0.8 Mil Dia., Au		
Leadframe (Finish, Base):	NiPdAu, Cu	NiPdAu, Cu		
MSL:	JEDEC L-1/260C	JEDEC L-1/260C		
信頼性試験結果				
Reliability Test	Condition / Duration	Sample Size/ Fails		
		Device1	Device2	
Electrical Characterization	Full Temp & Voltage range	Approved	Approved	
**Autoclave	121C, 96 Hrs	77/0	77/0	
**T/C	-65C/150C, 500 Cyc	87/0	86/0	
Surface Mount Solderability	8 Hrs Steam	22/0	22/0	
Bond Pull	76 ball bonds, min. 3 units	5/0	5/0	
Moisture Sensitivity	JEDEC L-1/260C	22/0	22/0	
Manufacturability (Assembly)	per mfg. Site specification	Approved	Approved	
Note: ** Preconditioning sequence: JEDEC L-1/260C				

信頼性試験結果				
信頼性試験期間	開始	—	終了	2010 年 3 月 30 日
信頼性試験 — 試料構成詳細				
Qual Device:	OPA365AIDBV		-	-
Assembly Site:	NFME	Package/Code/Pins:	SOT/DBV/5	
Mount Compound:	A-03	Mold Compound:	R-13	
Bond Wire:	1.0 Mil Dia., Au	Leadframe (Finish, Base):	NiPdAu, Cu	
MSL:	JEDEC L-1/260C		-	-
信頼性試験結果				
Reliability Test	Condition / Duration		Sample Size/ Fails	
**High Temp. Storage Bake	170C, 420 Hours		77/0	
**Autoclave	121C, 96 Hrs		77/0	
**T/C	-65C/150C, 500 Cyc		80/0	
Visual / Mechanical	Performed during Assembly MQ		Approved	
Surface Mount Solderability	Pb Solder		22/0	
Lead Fatigue	22 leads, min. 3 units		22/0	
Lead Pull	22 leads to destruction, min. 3 units		22/0	
Lead Finish Adhesion	-		15/0	
Physical Dimensions	per mechanical drawing		5/0	
Ball Bond Shear	Wires		78/0	
Bond Pull	Wires		78/0	
Die Shear	-		10/0	
Manufacturability (Assembly)	per mfg. Site specification		Approved	
**Thermal Shock	-65C/150C, 500 Cyc		77/0	
Salt Atmosphere	24 Hrs		22/0	
X-ray	top side only		5/0	
Moisture Sensitivity	JEDEC L-1/260C		12/0	
Note: ** Preconditioning sequence: JEDEC L-1/260C				

Reference Qual #2

信頼性試験結果				
信頼性試験期間	開始	—	終了	2011 年 7 月 18 日
信頼性試験 - 試料構成詳細				
ID:	Device1	Device2	Device3	
Qual Device:	OPA330AIDCK	TMP330AIDCK	TPS71719DCK	
Assembly Site:	NFME	NFME	NFME	
Package/Code/Pins:	SOT/DCK/5	SOT/DCK/6	SOT/DCK/5	
Mount Compound:	A-03	A-03	A-03	
Mold Compound:	R-07	R-07	R-07	
Bond Wire:	1.0 Mil Dia., Au	1.0 Mil Dia., Au	1.0 Mil Dia., Au	
Leadframe (Finish, Base):	NiPdAu, Cu	NiPdAu, Cu	NiPdAu, Cu	
MSL:	JEDEC L-1/260C	JEDEC L-1/260C	JEDEC L-1/260C	
信頼性試験結果				
Reliability Test	Condition / Duration	Sample Size/ Fails		
		Device1	Device2	Device3
**High Temp. Storage Bake	170C, 420hrs	77/0	77/0	-
Electrical Characterization	Over Temp	-	-	Approved
**Unbiased HAST	130C/85%RH, 96 Hrs	77/0	77/0	77/0
**T/C	-65C/150C, 500 Cyc	77/0	77/0	77/0
Solderability	Steam age, 8 hours	22/0	22/0	-
Lead Pull	# of leads to destruction, min. 3 units	22/0	22/0	22/0
Lead Fatigue	# of leads, min. 3 units	22/0	22/0	22/0
Lead Finish Adhesion	# of leads, min. 3 units	15/0	15/0	15/0
Manufacturability	per mfg. Site specification	Approved	Approved	Approved
X-ray	top side only	5/0	5/0	-
Moisture Sensitivity	JEDEC L-1/260C	12/0	12/0	12/0
Notes: ** Preconditioning sequence: JEDEC L-1/260C				

信頼性試験結果				
信頼性試験期間	開始	—	終了	2006 年 10 月 4 日
信頼性試験 - 試料構成詳細				
Qual Device:	LPV321DCKR	-	-	
Assembly Site:	NFME	Package Code/Pins:	DCK/5	
Mount Compound:	A-03	Mold Compound:	R-07	
Bond Wire:	1.0 mil Dia., Au	Leadframe (Finish, Base):	NiPdAu, Cu	
信頼性試験結果				
Reliability Test	Condition / Duration	Sample Size/ Fails		
		Lot #1	Lot #2	Lot #3
**High Temp Operating Life	150C, 300 hours	40/0	40/0	40/0
**Biased HAST	130C/85%RH, 96 hours	26/0	26/0	26/0
**Autoclave	121C, 96 Hrs	77/0	77/0	77/0
**Temperature Cycle	-65C/150C, 500 Cyc	77/0	77/0	77/0
**Thermal Shock	-65C/150C, 500 Cyc	77/0	77/0	77/0
**Storage Bake	170C, 1000 hours	77/0	77/0	77/0
Lead Pull	-	22/0	22/0	22/0
Flammability	UL 94V-0	5/0	5/0	5/0
Flammability	UL-1694	5/0	5/0	5/0
Flammability	IEC 695-2-2	5/0	5/0	5/0
X-RAY	top side only	5/0	5/0	5/0
Visual / Mechanical	-	Approved	Approved	Approved
Moisture Sensitivity	JEDEC L-1/260C	7/0	8/0	8/0
Note: ** Preconditioning sequence JEDEC L-1/260C				

Reference Qual #3

信頼性試験結果				
信頼性試験期間	開始	—	終了	2007 年 1 月 30 日
信頼性試験 - 試料構成詳細				
Qual Device:	LM317DCY	-	-	
Assembly Site:	NFME	Package/Code/Pins:	SOT/DCY/4	
Mount Compound:	A-06	Mold Compound:	R-07	
Bond Wire:	2.0 mil Dia., Au	Leadframe (Finish, Base):	Matte Sn, Cu	
MSL:	JEDEC L-2/260C	-	-	
信頼性試験結果				
Reliability Test	Condition / Duration	Sample Size/ Fails		
		Lot #1	Lot #2	Lot #3
** High Temp Operating Life	150C, 300 hours	40/0	40/0	40/0
** Biased HAST	130C/85%RH, 96 hours	26/0	26/0	26/0
** Autoclave	121C, 96 Hrs	77/0	77/0	77/0
** Temp Cycle	-65C/150C, 500 Cyc	77/0	77/0	77/0
** Storage Bake	150C, 1000 hours	77/0	77/0	77/0
Solderability	8 Hours Steam Age	22/0	22/0	22/0
Lead Finish Adhesion	-	15/0	15/0	15/0
Lead Pull	-	22/0	22/0	22/0
Lead Integrity	-	22/0	22/0	22/0
Flammability	UL 94V-0	5/0	5/0	5/0
Flammability	UL-1694	5/0	5/0	5/0
Flammability	IEC 695-2-2	5/0	5/0	5/0
X-RAY	-	5/0	5/0	5/0
Physical Dimensions	-	5/0	5/0	5/0
Ball Bond Shear	-	78/0	78/0	78/0
Wire Pull	-	78/0	78/0	78/0
Die Shear	-	10/0	10/0	10/0
Salt Atmosphere	-	22/0	22/0	22/0
Moisture Sensitivity	JEDEC L-2/260C	12/0	12/0	12/0
Manufacturability	-	Approved	Approved	Approved
Note: ** Preconditioning Sequence: JEDEC L-2/260C				

Reference Qual #4

信頼性試験結果				
信頼性試験期間	開始	—	終了	2011 年 7 月 18 日
信頼性試験 - 試料構成詳細				
Qual Device:	TLV70228DBV	-	-	
Assembly Site:	NS2	Package/Code/Pins:	SOT/DBV/5	
Mount Compound:	PZ0001	Mold Compound:	R-13	
Leadframe (Finish,Base):	NiPdAu, Cu	MSL:	JEDEC L-1/260C	
信頼性試験結果				
Reliability Test	Condition / Duration	Sample Size/ Fails		
		Lot #1	Lot #2	Lot #3
HTOL High Temp. Op Life	140C, 48, 324 Hrs	116/0	116/0	116/0
Electrical Characterization	-	30/0	30/0	30/0
**Autoclave	121C, 96 Hrs	77/0	77/0	77/0
**T/C	-65C/150C, 500 Cyc	77/0	77/0	77/0
ESD CDM	500V	3/0	3/0	3/0
Process Characterization	BG, Die-saw & Die attach	Approved	Approved	Approved
Visual / Mechanical	Post Die-saw	328/0	328/0	328/0
Bond Strength	76 ball bonds, min. 3 units	76/0	76/0	76/0
Die Shear	-	10/0	10/0	10/0
Destructive Physical Analysis	Pre-stress	2/0	2/0	2/0
Manufacturability	per mfg. Site specification	Approved	Approved	Approved
X-ray	top side only	5/0	5/0	5/0
Moisture Sensitivity	JEDEC L-1/260C	12/0	12/0	12/0
Note: ** Preconditioning sequence: JEDEC L-1/260C				

Reference Qual #5

信賴性試驗結果				
信賴性試驗期間	開始	—	終了	2008 年 5 月 20 日
信賴性試驗 - 試料構成詳細				
Qual Device:	OPA379AIDCK	-	-	
Assembly Site:	NSE	Package/Code/Pins:	SOT/DCK/5	
Mount Compound:	A-09	Mold Compound:	R-13	
Bond Wire:	1.0 mil Dia., Au	Leadframe (Finish,Base):	NiPdAu, Cu	
MSL:	JEDEC L-2/260C	-	-	
信賴性試驗結果				
Reliability Test	Condition / Duration		Sample Size/ Fails	
** Autoclave	121C, 96 Hrs		77/0	
** Temp Cycle	-65C/150C, 500 cycles		77/0	
Visual/Mechanical	Per final visual inspection criteria		Approved	
Bond Strength	76 ball bonds, min. 3 units		76/0	
Die Shear	-		10/0	
Manufacturability	per mfg. Site specification		Approved	
X-Ray	Top Side Only		5/0	
Moisture Sensitivity	JEDEC L-2/260C		10/0	
Note: ** Preconditioning Sequence: JEDEC L-2/260C				

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信頼性試験結果				
信頼性試験期間	開始	—	終了	2004 年 8 月 10 日
信頼性試験 - 試料構成詳細				
Qual Device:	TS5A3159IM	-	-	
Assembly Site:	NSE	Package/Code/Pins:	SOT/DCK/6	
Mount Compound:	A-09	Mold Compound:	R-13	
Bond Wire:	1.0 mil Dia., Au	Leadframe (Finish,Base):	NiPdAu, Cu	
MSL:	JEDEC L-1/260C	-	-	
信頼性試験結果				
Reliability Test	Condition / Duration	Sample Size/ Fails		
		Lot #1	Lot #2	Lot #3
**High Temp Operating Life	150C, 300 hours	40/0	40/0	40/0
**Biased HAST	130C/85%RH, 300 hours	26/0	26/0	26/0
** Autoclave	121C, 96 Hrs	77/0	77/0	77/0
** Temp Cycle	-65C/150C, 500 cycles	77/0	77/0	77/0
**Thermal Shock	-65C/150C, 500 cycles	77/0	77/0	77/0
**Storage Bake	17C, 420 hours	77/0	77/0	77/0
Solderability	-	22/0	22/0	22/0
Lead Pull	-	22/0	22/0	22/0
Lead Integrity	-	22/0	22/0	22/0
X-Ray	Top Side Only	5/0	5/0	5/0
Moisture Sensitivity	JEDEC L-1/260C	12/0	-	-
Note: ** Preconditioning Sequence: JEDEC L-1/260C				

信頼性試験結果				
信頼性試験期間	開始	—	終了	2006 年 6 月 22 日
信頼性試験 - 試料構成詳細				
Qual Device:	SN200604024DCK	-	-	
Assembly Site:	NSE	Package/Code/Pins:	SOT/DCK/6	
Mount Compound:	A-09	Mold Compound:	R-13	
Bond Wire:	1.0 mil Dia., Au	Leadframe (Finish,Base):	NiPdAu, Cu	
MSL:	JEDEC L-1/260C	-	-	
信頼性試験結果				
Reliability Test	Condition / Duration	Sample Size/ Fails		
		Lot #1	Lot #2	Lot #3
**High Temp Operating Life	150C, 300 hours	116/0	-	-
Electrical Characterization	-	Approved	-	-
** Autoclave	121C, 96 Hrs	77/0	77/0	77/0
** Temp Cycle	-65C/150C, 500 cycles	77/0	77/0	77/0
ESD HBM	2000V	3/0	-	-
ESD CDM	500V	3/0	-	-
Latch-up	per JEESD78	6/0	-	-
Manufacturability	per mfg. Site specification	Approved	-	-
X-Ray	Top Side Only	5/0	-	-
Moisture Sensitivity	JEDEC L-1/260C	12/0	-	-
Note: ** Preconditioning Sequence: JEDEC L-1/260C				

信頼性試験結果				
信頼性試験期間	開始	—	終了	2008 年 5 月 2 日
信頼性試験 - 試料構成詳細				
Qual Device:	TL4050C10IDCKR	-	-	
Assembly Site:	NS2	Package/Code/Pins:	SOT/DCK/5	
Mount Compound:	A-09	Mold Compound:	R-13	
Bond Wire:	1.0 mil Dia., Au	Leadframe (Finish,Base):	NiPdAu, Cu	
MSL:	JEDEC L-1/260C	-	-	
信頼性試験結果				
Reliability Test	Condition / Duration	Sample Size/ Fails		
		Lot #1	Lot #2	Lot #3
** Autoclave	121C, 96 Hrs	77/0	77/0	77/0
** Temp Cycle	-65C/150C, 500 cycles	77/0	77/0	77/0
Physical Dimensions	per mechanical drawing	5/0	5/0	5/0
Bond Strength	76 ball bonds, min. 3 units	76/0	76/0	76/0
Die Shear	-	10/0	10/0	10/0
Manufacturability	per mfg. Site specification	Approved	Approved	Approved
X-Ray	Top Side Only	5/0	5/0	5/0
Moisture Sensitivity	JEDEC L-1/260C	12/0	12/0	12/0
Note: ** Preconditioning Sequence: JEDEC L-1/260C				

Reference Qual #6

信頼性試験結果				
信頼性試験期間	開始	—	終了	2008 年 5 月 20 日
信頼性試験 - 試料構成詳細				
Qual Device:	REF3112AIDBZ	-	-	
Assembly Site:	NS2	Package/Code/Pins:	SOT/DBZ/3	
Mount Compound:	A-09	Mold Compound:	R-13	
Bond Wire:	1.0 mil Dia., Au	Leadframe (Finish,Base):	NiPdAu, Cu	
MSL:	JEDEC L-2/260C	-	-	
信頼性試験結果				
Reliability Test	Condition / Duration		Sample Size/ Fails	
** Autoclave	121C, 96 Hrs		77/0	
** Temp Cycle	-65C/150C, 500 cycles		77/0	
Visual/Mechanical	Per final visual inspection criteria		Approved	
Bond Strength	76 ball bonds, min. 3 units		76/0	
Die Shear	-		10/0	
Manufacturability	per mfg. Site specification		Approved	
X-Ray	Top Side Only		5/0	
Moisture Sensitivity	JEDEC L-2/260C		10/0	
Note: ** Preconditioning Sequence: JEDEC L-2/260C				

信頼性試験結果				
信頼性試験期間	開始	—	終了	2004 年 8 月 10 日
信頼性試験 — 試料構成詳細				
Qual Device:	TS5A3159IM	-	-	
Assembly Site:	NSE	Package/Code/Pins:	SOT/DBZ/6	
Mount Compound:	A-09	Mold Compound:	R-13	
Bond Wire:	1.0 mil Dia., Au	Leadframe (Finish,Base):	NiPdAu, Cu	
MSL:	JEDEC L-1/260C	-	-	
信頼性試験結果				
Reliability Test	Condition / Duration		Sample Size/ Fails	
** Autoclave	121C, 96 Hrs		77/0	
** Temp Cycle	-65C/150C, 500 cycles		77/0	
Visual/Mechanical	Per final visual inspection criteria		Approved	
Bond Strength	76 ball bonds, min. 3 units		76/0	
Die Shear	-		10/0	
Manufacturability	per mfg. Site specification		Approved	
X-Ray	Top Side Only		5/0	
Moisture Sensitivity	JEDEC L-1/260C		10/0	
Note: ** Preconditioning Sequence: JEDEC L-1/260C				

Reference Qual #7

信頼性試験結果

信頼性試験期間	開始	—	終了	2008 年 8 月 13 日
信頼性試験 - 試料構成詳細				
Qual Device:	INA219AIDCN	-	-	
Assembly Site:	NSE	Package/Code/Pins:	SOT23/DCN/8	
Mount Compound:	A-09	Mold Compound:	R-13	
Bond Wire:	1.0 mil Dia., Au	Leadframe (Finish,Base):	NiPdAu, Cu	
MSL:	JEDEC L-2/260C	-	-	
信頼性試験結果				
Reliability Test	Condition / Duration		Sample Size/ Fails	
**Life Test	150C, 300 Hrs		116/0	
Electrical Characterization	-		Approved	
**Biased HAST	130C/85%RH, 96 Hrs		77/0	
** Autoclave	121C, 96 Hrs		77/0	
** Temp Cycle	-65C/150C, 1000 cycles		77/0	
ESD HBM	2000V		3/0	
ESD CDM	500V		3/0	
Thermal Impedance	-		5/0	
Electro-migration	-		Approved	
Hot Electron Injection	-		Approved	
Latch-up	per JESD78		6/0	
Manufacturability	per mfg. Site specification		Approved	
X-Ray	Top Side Only		5/0	
Moisture Sensitivity	JEDEC L-2/260C		10/0	
Note: ** Preconditioning Sequence: JEDEC L-2/260C				

信頼性試験結果				
信頼性試験期間	開始	—	終了	2007 年 7 月 12 日
信頼性試験 - 試料構成詳細				
Qual Device:	TMP421AIDCN	-	-	
Assembly Site:	NSE	Package/Code/Pins:	SSOP/DCN/8	
Mount Compound:	A-09	Mold Compound:	R-13	
Bond Wire:	1.0 mil Dia., Au	Leadframe (Finish,Base):	NiPdAu, Cu	
MSL:	JEDEC L-2/260C	-	-	
信頼性試験結果				
Reliability Test	Condition / Duration		Sample Size/ Fails	
** Autoclave	121C, 240 hours		79/0	
** Temp Cycle	-65C/150C, 1000 cycles		80/0	
ESD CDM	500V		3/0	
X-Ray	Top Side Only		5/0	
Note: ** Preconditioning Sequence: JEDEC L-2/260C				

Reference Qual #8

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信頼性試験結果				
信頼性試験期間	開始	—	終了	2011 年 10 月 18 日
信頼性試験 - 試料構成詳細				
Qual Device:	TPS781250200DDC	-	-	
Assembly Site:	NS2 (UTAC2)	Package/Code/Pins:	TSOT-23/DDC/5	
Mount Compound:	PZ0013	Mold Compound:	R-13	
Bond Wire:	1.3 mil Dia., Au	Leadframe (Finish, Base):	NiPdAu, Cu	
MSL:	JEDEC L-2/260C	-	-	
信頼性試験結果				
Reliability Test	Condition / Duration		Sample Size/ Fails	
** High Temp Operating Life	150C, 300 Hrs		116/0	
Electrical Characterization	-		30/0	
** Autoclave	121C, 96 Hrs		77/0	
** T/C	-65C/150C, 500 Cyc		77/0	
ESD HBM	2000V		3/0	
ESD CDM	500V		3/0	
Latchup	-		6/0	
Manufacturability (Assembly)	per mfg. Site specification		Approved	
Moisture Sensitivity	JEDEC L-2/260C		12/0	
FTY and Bin Summary	-		Approved	
Notes: ** Tests require preconditioning sequence: JEDEC L-2/260C				

信頼性試験結果				
信頼性試験期間	開始	—	終了	2008 年 3 月 24 日
信頼性試験 - 試料構成詳細				
Qual Device:	TPS78001DDC	-	-	
Assembly Site:	UTAC/NSE	Package/Code/Pins:	SOT/DDC/5	
Mount Compound:	PZ0013	Mold Compound:	R-13	
Bond Wire:	1.3 mil Dia., Au	Leadframe (Finish,Base):	NiPdAu, Cu	
MSL:	JEDEC L-2/260C	-	-	
信頼性試験結果				
Reliability Test	Condition / Duration	Sample Size/ Fails		
		Lot #1	Lot #2	Lot #3
**High Temp Operating Life	150C, 300 Hrs	116/0	-	-
Electrical Char.	-	15/0	-	-
**Biased HAST	130C/85%RH, 96, 192 Hrs	77/0	-	-
**Autoclave	121C, 96 Hrs	77/0	77/0	77/0
**T/C	-65C/150C, 500 Cyc	77/0	77/0	77/0
ESD HBM	2000V	3/0	-	-
ESD CDM	500V	3/0	-	-
Latch-up	per JEESD78	6/0	-	-
Manufacturability	per mfg. Site specification	Approved	-	-
Moisture Sensitivity	JEDEC L-2/260C	12/0	-	-
Note: ** Preconditioning sequence JEDEC L-2/260C				

信頼性試験結果				
信頼性試験期間	開始	—	終了	2008 年 3 月 24 日
信頼性試験 - 試料構成詳細				
Qual Device:	TPS780330220DDC	-	-	
Assembly Site:	UTAC/NSE	Package/Code/Pins:	SOT/DDC/5	
Mount Compound:	PZ0013	Mold Compound:	R-13	
Bond Wire:	1.3 mil Dia., Au	Leadframe (Finish,Base):	NiPdAu, Cu	
MSL:	JEDEC L-2/260C	-	-	
信頼性試験結果				
Reliability Test	Condition / Duration	Sample Size/ Fails		
		Lot #1	Lot #2	Lot #3
**High Temp Operating Life	150C, 300 Hrs	116/0	-	-
Electrical Characterization	Full Temperature	15/0	-	-
**Biased HAST	130C/85%RH, 96 Hrs	77/0	-	-
**Autoclave	121C, 96 Hrs	77/0	77/0	77/0
**T/C	-65C/150C, 500 Cyc	77/0	-	-
ESD HBM	2000V	3/0	-	-
ESD CDM	500V	3/0	-	-
Latch-up	per JEDEC78	6/0	-	-
Manufacturability	per mfg. Site specification	Approved	-	-
Moisture Sensitivity	JEDEC L-2/260C	12/0	-	-
Note: ** Preconditioning sequence JEDEC L-2/260C				

Reference Qual #9

信頼性試験結果				
信頼性試験期間	開始	—	終了	2010 年 1 月 22 日
信頼性試験 - 試料構成詳細				
Qual Device:	SN74LVC1G14DBVR	-	-	
Assembly Site:	ASEWH	Package/Code/Pins:	SOT/DBV/5	
Mount Compound:	1120999A1	Mold Compound:	R-13	
Bond Wire:	0.8 mil Dia. Au	Leadframe (Finish,Base):	NiPdAu, Cu	
MSL:	JEDEC L-1/260C	-	-	
信頼性試験結果				
Reliability Test	Condition / Duration	Sample Size/ Fails		
		Lot #1	Lot #2	Lot #3
Electrical Char.	-	Approved	Approved	Approved
High Temp. Storage Bake	170C, 420 Hrs	77/0	77/0	77/0
**Autoclave	121C, 96 Hrs	77/0	77/0	77/0
**T/C	-65C/150C, 500 Cyc	77/0	77/0	77/0
Thermal Shock	-65C/150C, 500 Cyc	77/0	77/0	77/0
Bond Strength	76 ball bonds, min. 3 units	76/0	76/0	76/0
Die Shear	-	10/0	10/0	10/0
Manufacturability (Assembly)	per mfg. Site specification	Approved	Approved	Approved
X-Ray	-	5/0	5/0	5/0
Moisture Sensitivity	-	12/0	12/0	12/0
Note: ** must be preconditioned per the appropriate sequence, JEDEC L-1/260C				

信頼性試験結果				
信頼性試験期間	開始	—	終了	2010年1月22日
信頼性試験 - 試料構成詳細				
Qual Device:	TL431CDBVR	-	-	
Assembly Site:	ASEWH	Package/Code/Pins:	SOT/DBV/5	
Mount Compound:	1120999A1	Mold Compound:	R-13	
Bond Wire:	1.0 mil Dia. Au	Leadframe (Finish,Base):	NiPdAu, Cu	
MSL:	JEDEC L-1/260C	-	-	
信頼性試験結果				
Reliability Test	Condition / Duration	Sample Size/ Fails		
		Lot #1	Lot #2	Lot #3
**High Temp Operating Life	150C, 300 Hrs	77/0	77/0	77/0
Electrical Char.	-	Approved	Approved	Approved
**High Temp. Storage Bake	150C, 500 Hrs	77/0	77/0	77/0
**Biased HAST	130C/85%RH, 96 Hrs	77/0	77/0	77/0
**Autoclave	121C, 96 Hrs	77/0	77/0	77/0
**T/C	-65C/150C, 500 Cyc	77/0	77/0	77/0
Thermal Shock	-65C/150C, 500 Cyc	77/0	77/0	77/0
Solderability	Steam age, 8 hours	22/0	22/0	22/0
Lead Pull	-	22/0	22/0	22/0
Lead Fatigue	-	22/0	22/0	22/0
Lead Finish Adhesion	-	15/0	15/0	15/0
Physical Dimensions	-	5/0	5/0	5/0
Flammability	-	5/0	5/0	5/0
Bond Strength	76 ball bonds, min. 3 units	76/0	76/0	76/0
Die Shear	-	10/0	10/0	10/0
X-Ray	-	5/0	5/0	5/0
Moisture Sensitivity	-	12/0	12/0	12/0
Manufacturability (Assembly)	per mfg. Site specification	Approved	Approved	Approved
Note: ** must be preconditioned per appropriate sequence JEDEC L-1/260C				

Reference Qual #10

信頼性試験結果				
信頼性試験期間	開始	—	終了	2010年1月22日
信頼性試験 - 試料構成詳細				
Qual Device:	LMV721IDCKR	-	-	
Assembly Site:	ASEWH	Package/Code/Pins:	SC70/DCK/5	
Mount Compound:	1120999A1	Mold Compound:	R-13	
Bond Wire:	1.0 mil Dia. Au	Leadframe (Finish,Base):	NiPdAu, Cu	
MSL:	JEDEC L-1/260C	-	-	
信頼性試験結果				
Reliability Test	Condition / Duration	Sample Size/ Fails		
		Lot #1	Lot #2	Lot #3
**High Temp Operating Life	150C, 300 Hrs	77/0	77/0	77/0
**Biased HAST	130C/85%RH, 96 Hrs	77/0	77/0	77/0
**Autoclave	121C, 96 Hrs	77/0	77/0	77/0
**T/C	-65C/150C, 500 Cyc	77/0	77/0	77/0
**Thermal Shock	-65C/150C, 500 Cyc	77/0	77/0	77/0
High Temp. Storage Bake	150C, 500 Hrs	77/0	77/0	77/0
Solderability	Steam age, 8 hours	22/0	22/0	22/0
Flammability	Method A – UL 94-0	5/0	5/0	5/0
Flammability	Method B – IEC 695-2-2	5/0	5/0	5/0
Flammability	Method C – UL 1694	5/0	5/0	5/0
Lead Pull	# of leads to destruction, min. 3 Units	22/0	22/0	22/0
Lead Fatigue	# of leads, min. 3 Units	22/0	22/0	22/0
Lead Finish Adhesion	# of leads, min. 3 Units	15/0	15/0	15/0
Physical Dimensions	-	5/0	5/0	5/0
Bond Strength	76 ball bonds, min. 3 units	76/0	76/0	76/0
Die Shear	-	10/0	10/0	10/0
X-Ray	-	5/0	5/0	5/0
Moisture Sensitivity	JEDEC L-1/260C	12/0	12/0	12/0
Electrical Characterization	-	Approved	Approved	Approved
Manufacturability (Assembly)	per mfg. Site specification	Approved	Approved	Approved
Notes: ** Tests require preconditioning sequence: JEDEC L-1/260C				

信頼性試験結果				
信頼性試験期間	開始	—	終了	2010 年 1 月 22 日
信頼性試験 - 試料構成詳細				
Qual Device:	SN74LVC2G14DCKR	-	-	
Assembly Site:	ASEWH	Package/Code/Pins:	SC70/DCK/6	
Mount Compound:	1120999A1	Mold Compound:	R-13	
Bond Wire:	0.8 mil Dia. Au	Leadframe (Finish,Base):	NiPdAu, Cu	
MSL:	JEDEC L-1/260C	-	-	
信頼性試験結果				
Reliability Test	Condition / Duration	Sample Size/ Fails		
		Lot #1	Lot #2	Lot #3
Electrical Characterization	-	Approved	Approved	Approved
**High Temp. Storage Bake	150C, 1000 Hrs	77/0	77/0	77/0
**Autoclave	121C, 96 Hrs	77/0	77/0	77/0
**T/C	-65C/150C, 500 Cyc	77/0	77/0	77/0
**Thermal Shock	-65C/150C, 1000 Cyc	77/0	77/0	77/0
Bond Strength	76 ball bonds, min. 3 units	76/0	76/0	76/0
Die Shear	-	10/0	10/0	10/0
X-Ray	-	5/0	5/0	5/0
Moisture Sensitivity	JEDEC L-1/260C	12/0	12/0	12/0
Manufacturability (Assembly)	per mfg. Site specification	Approved	-	-
Notes: ** Tests require preconditioning sequence: JEDEC L-1/260C				

Reference Qual #11

信頼性試験結果				
信頼性試験期間	開始	—	終了	2010 年 1 月 22 日
信頼性試験 - 試料構成詳細				
Qual Device:	TLV431BIDBZR	-	-	
Assembly Site:	ASEWH	Package/Code/Pins:	SOT/DBZ/3	
Mount Compound:	1120999A1	Mold Compound:	R-13	
Bond Wire:	1.0 mil Dia. Au	Leadframe (Finish,Base):	NiPdAu, Cu	
MSL:	JEDEC L-1/260C	-	-	
信頼性試験結果				
Reliability Test	Condition / Duration	Sample Size/ Fails		
		Lot #1	Lot #2	Lot #3
**Life Test	150C, 300 Hrs	77/0	77/0	77/0
Electrical Char.	-	Approved	Approved	Approved
**High Temp. Storage Bake	170C, 420 Hrs	77/0	77/0	77/0
**Biased HAST	130C/85%RH, 96 Hrs	77/0	77/0	77/0
**Autoclave	121C, 96 Hrs	77/0	77/0	77/0
**T/C	-65C/150C, 500 Cyc	77/0	77/0	77/0
Thermal Shock	-65C/150C, 500 Cyc	77/0	77/0	77/0
Solderability	Steam age, 8 hours	22/0	22/0	22/0
Lead Pull	-	22/0	22/0	22/0
Lead Fatigue	-	22/0	22/0	22/0
Lead Finish Adhesion	-	15/0	15/0	15/0
Physical Dimensions	-	5/0	5/0	5/0
Flammability	-	5/0	5/0	5/0
Bond Strength	76 ball bonds, min. 3 units	76/0	76/0	76/0
Die Shear	-	10/0	10/0	10/0
X-Ray	-	5/0	5/0	5/0
Moisture Sensitivity	-	12/0	12/0	12/0
Manufacturability (Assembly)	per mfg. Site specification	Approved	Approved	Approved
Note: ** must be preconditioned per the appropriate sequence, JEDEC L-1/260C				

Reference Qual #12

信頼性試験結果				
信頼性試験期間	開始	—	終了	2008 年 5 月 30 日
信頼性試験 - 試料構成詳細				
Qual Device:	TPS40003DGQ	-	-	
Assembly Site:	NS2	Package/Code/Pins:	VSSOP/DGQ/10	
Mount Compound:	PZ0013	Mold Compound:	R-13	
Bond Wire:	1.0 mil Dia., Au	Leadframe (Finish, Base):	NiPdAu, Cu	
MSL:	JEDEC L-1/260C	-	-	
信頼性試験結果				
Reliability Test	Condition / Duration	Sample Size/ Fails		
		Lot #1	Lot #2	Lot #3
**Autoclave	121C, 96 Hrs	76/0	76/0	76/0
**T/C	-65C/150C, 250, 500 Cyc	76/0	76/0	76/0
Bond Strength	76 ball bonds, min. 3 units	76/0	76/0	76/0
Die Shear	-	10/0	10/0	10/0
Manufacturability	per mfg. Site specification	Approved	Approved	Approved
Moisture Sensitivity	JEDEC L-1/260C	12/0	12/0	12/0
Notes: ** Tests require preconditioning sequence: JEDEC L-1/260C				

信頼性試験結果				
信頼性試験期間	開始	—	終了	2005 年 6 月 7 日
信頼性試験 - 試料構成詳細				
ID:	Device1		Device2	
Qual Device:	UC2903N		UCC2801D	
Assembly Site:	NSE		NSE	
Package/Code/Pins:	PDIP/N/18		SOIC/D/8	
Mount Compound:	PZ0013		PZ0013	
Mold Compound:	R-13		R-13	
Leadframe finish:	NiPdAu		NiPdAu	
ID:	Device3		Device4	
Qual Device:	OPO7CD		SN0305028AIDBV	
Assembly Site:	NSE		NSE	
Package/Code/Pins:	SOIC/D/8		SOT/DBV/6	
Mount Compound:	PZ0001		PZ0001	
Mold Compound:	R-13		R-13	
Leadframe finish:	NiPdAu		NiPdAu	
信頼性試験結果				
Reliability Test	Condition / Duration	Sample Size/ Fails		
		Device1	Device2	
Life Test	125C, 1000Hrs.	348/0	-	
HAST	130C/85%RH, 96 Hrs.	231/0	-	
Autoclave	121C, 240 Hrs.	231/0	-	
Thermal Shock	-65C/150C, 1000 cycles	-	-	
Temp Cycle	-65C/150C, 1000 cycles	231/0	231/0	
High-Temp Storage	150C, 1000Hrs.	135/0	-	
X-Ray	Top side	Approved	Approved	
Lead Fatigue	-	Approved	-	
Solderability	8 hr steam age/flux/Dip	Approved	-	
Physical Dimensions	Per mechanical drawing	Approved	-	
Visual/Mechanical	-	Approved	Approved	
Salt Atmosphere	24 Hrs.	Approved	-	
Manufacturability (MQ)	Assembly Site	-	Approved	
Moisture Sensitivity	JEDEC L-1/260C	-	Approved	
Reliability Test	Condition / Duration	Sample Size/ Fails		
		Device3	Device4	
Life Test	125C, 1000Hrs.	103/0	116/0	
HAST	130C/85%RH, 96 Hrs.	231/0	98/0	
Autoclave	121C, 240 Hrs.	231/0	80/0	
Thermal Shock	-65C/150C, 1000 cycles	231/0	119/0	
Temp Cycle	-65C/150C, 1000 cycles	Note(1)	80/0	
High-Temp Storage	170C,420 Hrs.	135/0	-	
High-Temp Storage	150C, 1000Hrs.	-	49/0	
X-Ray	Top side	Approved	Approved	
Lead Fatigue	-	Approved	-	
Solvent Resistance	-	Note(1)	Note(1)	
Solderability	8 hr steam age/flux/Dip	Approved	Note(1)	
Physical Dimensions	Per mechanical drawing	Approved	Note(1)	
Flammability	UL94 Class V-0	Approved	Note(1)	
Visual/Mechanical	-	Approved	Note(1)	
Salt Atmosphere	24 Hrs.	Approved	Note(1)	
Manufacturability (MQ)	Assembly Site	Approved	Approved	
Moisture Sensitivity	JEDEC L-1/260C	Approved	Approved*	
Notes:				
* This device was previously classified at JEDEC L-2/260C.Subsequent testing has shown that this device is now classified at JEDEC L-1/260C.				
(1) NSE package qual data has been utilized				

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信頼性試験結果				
信頼性試験期間	開始	—	終了	2005 年 6 月 7 日
信頼性試験 - 試料構成詳細				
ID:	Device5	Device6	Device7	
Qual Device:	OPA690N/SN030711DBV	TPS62202DBV	OPA695IDBV	
Assembly Site:	NSE	NSE	NSE	
Package/Code/Pins:	SOT/DBV/6	SOT/DBV/5	SOT/DBV/6	
Mount Compound:	PZ0001	PZ0001	PZ0001	
Mold Compound:	R-13	R-13	R-13	
Leadframe finish:	NiPdAu	NiPdAu	NiPdAu	
ID:	Device8	Device9	-	
Qual Device:	TMP101NA	TLV2361CDBV	-	
Assembly Site:	NSE	NSE	-	
Package/Code/Pins:	SOT/DBV/6	SOT/DBV/5	-	
Mount Compound:	PZ0001	PZ0001	-	
Mold Compound:	R-13	R-13	-	
Leadframe finish:	NiPdAu	NiPdAu	-	
信頼性試験結果				
Reliability Test	Condition / Duration	Sample Size/ Fails		
		Device5	Device6	Device7
Life Test	125C, 1059Hrs.	-	-	118/0
	125C, 1000Hrs.	120/0	Note(1)	-
HAST	130C/85%RH, 96 Hrs.	98/0	Note(1)	97/0
Autoclave	121C, 240 Hrs.	98/0	154/0	98/0
Thermal Shock	-65C/150C, 1000 cycles	Note(1)	154/0	Note(1)
Temp Cycle	-65C/150C, 1000 cycles	98/0	154/0	98/0
High-Temp Storage	170C, 420 Hrs.	-	Note(1)	-
	150C, 1000Hrs.	49/0	-	49/0
X-Ray	Top side	Approved	Note(1)	Approved
Solvent Resistance	-	Note(1)	Note(1)	Note(1)
Solderability	8 hr steam age/flux/Dip	Note(1)	Note(1)	Note(1)
Physical Dimensions	Per mechanical drawing	Note(1)	Note(1)	Note(1)
Flammability	UL94 Class V-0	Note(1)	Note(1)	Note(1)
Visual/Mechanical	-	Note(1)	Note(1)	Note(1)
Salt Atmosphere	24 Hrs.	Note(1)	Note(1)	Note(1)
Manufacturability (MQ)	Assembly Site	Approved	Approved	Approved
Moisture Sensitivity	JEDEC L-1/260C	Approved*	Approved	Approved*
Reliability Test	Condition / Duration	Sample Size/ Fails		
		Device8	Device9	-
Life Test	150C, 300Hrs.	116/0	-	-
	150C, 500 Hrs	-	120/0	-
HAST	130C/85%RH, 96 Hrs.	80/0	78/0	-
Autoclave	121C, 96 Hrs.	-	231/0	-
	121C, 240 Hrs.	80/0	-	-
Thermal Shock	-65C/150C, 1000 cycles	Note(1)	231/0	-
Temp Cycle	-65C/150C, 1000 cycles	79/0	-	-
High-Temp Storage	170C, 420 Hrs.	Note(1)	135/0	-
X-Ray	Top side	Note(1)	Approved	-
Solvent Resistance	-	Note(1)	-	-
Solderability	8 hr steam age/flux/Dip	Note(1)	Approved	-
Physical Dimensions	Per mechanical drawing	Note(1)	Approved	-
Flammability	UL94 Class V-0	Approved	Approved	-
Visual/Mechanical	-	Note(1)	-	-
Salt Atmosphere	24 Hrs.	Note(1)	Approved	-
Manufacturability (MQ)	Assembly Site	Approved	Approved	-
Moisture Sensitivity	JEDEC L-1/260C	Approved*	Approved	-
Notes:				
* This device was previously classified at JEDEC L-2/260C. Subsequent testing has shown that this device is now classified at JEDEC L-1/260C.				
(1) NSE package qual data has been utilized				

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信頼性試験結果				
信頼性試験期間	開始	—	終了	2005 年 6 月 7 日
信頼性試験 - 試料構成詳細				
ID:	Device10	Device11	Device12	
Qual Device:	TPS61040DBV(BOAC)	BQ2022DBZ	REF2912AIDBZ	
Assembly Site:	NSE	NSE	NSE	
Package/Code/Pins:	SOT/DBV/5	SOP/DBZ/3	SOP/DBZ/3	
Mount Compound:	PZ0013	PZ0001	PZ0001	
Mold Compound:	R-13	R-13	R-13	
Leadframe finish:	NiPdAu	NiPdAu	NiPdAu	
ID:	Device13	Device14	Device15	
Qual Device:	UCC2809PW-2	TPS2491DGS	TPS60300DGS	
Assembly Site:	NSE	NSE	NSE	
Package/Code/Pins:	TSSOP/PW/8	VSSOP/DGS/10	VSSOP/DGS/10	
Mount Compound:	PZ0013	PZ0013	PZ0013	
Mold Compound:	R-13	R-13	R-13	
Leadframe finish:	NiPdAu	NiPdAu	NiPdAu	
信頼性試験結果				
Reliability Test	Condition / Duration	Sample Size/ Fails		
		Device10	Device11	Device12
Life Test	150C, 300Hrs.	-	-	120/0
	155C, 240Hrs.	-	348/0	-
	140C, 480Hrs.	120/0	-	-
HAST	130C/85%RH, 96 Hrs.	231/0	231/0	80/0
Autoclave	121C, 240 Hrs.	231/0	231/0	85/0
Thermal Shock	-65C/150C, 1000 cycles	231/0	231/0	95/0
Temp Cycle	-65C/150C, 1000 cycles	231/0	231/0	89/0
High-Temp Storage	170C, 420 Hrs.	231/0	231/0	-
X-Ray	Top side	Approved	Note(1)	Approved
Lead Fatigue	-	Approved	Approved	Approved
Solvent Resistance	-	Approved	Approved	Note(1)
Solderability	8 hr steam age/flux/Dip	Approved	Approved	Approved
Physical Dimensions	Per mechanical drawing	Approved	Approved	Approved
Flammability	UL94 Class V-0	Approved	Approved	Approved
Visual/Mechanical	-	Note(1)	Approved	Approved
Salt Atmosphere	24 Hrs.	Approved	Approved	Approved
Manufacturability (MQ)	Assembly Site	Approved	Approved	Approved
Moisture Sensitivity	JEDEC L-1/260C	Approved	Approved	Approved*
Reliability Test	Condition / Duration	Sample Size/ Fails		
		Device13	Device14	Device15
Life Test	125C, 1000Hrs.	348/0	-	-
	150C, 300Hrs.	-	-	120/0
	155C, 240Hrs.	-	348/0	-
HAST	130C/85%RH, 96 Hrs.	231/0	231/0	120/0
Autoclave	121C, 96 Hrs.	231/0	-	-
	121C, 240 Hrs.	-	231/0	231/0
Thermal Shock	-65C/150C, 1000 cycles	-	231/0	231/0
Temp Cycle	-65C/150C, 1000 cycles	231/0	231/0	231/0
High-Temp Storage	170C, 420 Hrs.	-	231/0	78/0
	150C, 1000Hrs.	135/0	-	-
X-Ray	Top side	Approved	Approved	Note(1)
Lead Fatigue	-	Approved	Approved	Note(1)
Solvent Resistance	-	Note(1)	Approved	Note(1)
Solderability	8 hr steam age/flux/Dip	Approved	Approved	Note(1)
Physical Dimensions	Per mechanical drawing	Approved	Approved	Note(1)
Flammability	UL94 Class V-0	Approved	Approved	Note(1)
Visual/Mechanical	-	Approved	Approved	Note(1)
Salt Atmosphere	24 Hrs.	Approved	Approved	Note(1)
Manufacturability (MQ)	Assembly Site	Approved	Approved	Approved
Moisture Sensitivity	JEDEC L-1/260C	-	-	Approved
Moisture Sensitivity	JEDEC L-2/260C	Approved	Approved	-
Notes:				
* This device was previously classified at JEDEC L-2/260C. Subsequent testing has shown that this device is now classified at JEDEC L-1/260C.				
(1) NSE package qual data has been utilized				

Reference Qual #13

信頼性試験結果				
信頼性試験期間	開始	—	終了	2010 年 12 月 1 日
信頼性試験 - 試料構成詳細				
Qual Device:	TPS54327DDA	-	-	
Assembly Site:	ASE SHANGHAI	Package/Code/Pins:	HSOP/DDA/8	
Mount Compound:	EY1000063	Mold Compound:	EN2000509	
Bond Wire:	2.0 mil Dia., Cu	Leadframe (Finish, Base):	NiPdAu, Cu	
MSL:	JEDEC L-2/260C	-	-	
信頼性試験結果				
Reliability Test	Condition / Duration	Sample Size/ Fails		
		Lot #1	Lot #2	Lot #3
**High Temp Operating Life	125C, 1000 Hrs	26/0	26/0	26/0
Electrical Characterization	-	30/0	30/0	30/0
**Biased Temp Humidity	85C/85%RH, 1000 Hrs	26/0	26/0	26/0
**High Temp Storage Bake	150C, 1000 Hrs	77/0	77/0	77/0
**Autoclave	121C, 96 Hrs	77/0	77/0	77/0
**T/C	-65C/150C, 500 Cyc	77/0	77/0	77/0
Bond Strength	76 ball bonds, min. 3 units	76/0	76/0	76/0
Manufacturability (Assembly)	per mfg. Site specification	Approved	Approved	Approved
**Thermal Shock	-65C/150C, 200 Cyc	77/0	77/0	77/0
X-ray	top side only	5/0	5/0	5/0
Moisture Sensitivity Level	JEDEC L-2/260C	12/0	12/0	12/0
Notes: ** Tests require preconditioning sequence: JEDEC L-2/260C				

信頼性試験結果				
信頼性試験期間	開始	—	終了	2010 年 12 月 1 日
信頼性試験 - 試料構成詳細				
Qual Device:	TPS54327DDA ES1.1	-	-	
Assembly Site:	ASE SHANGHAI	Package/Code/Pins:	HSOP/DDA/8	
Mount Compound:	EY1000063	Mold Compound:	EN2000509	
Bond Wire:	2.0 mil Dia., Cu	Leadframe (Finish, Base):	NiPdAu, Cu	
MSL:	JEDEC L-2/260C	-	-	
信頼性試験結果				
Reliability Test	Condition / Duration		Sample Size/ Fails	
Electrical Characterization	-		30/0	
**T/C	-65C/150C, 500 Cyc		77/0	
ESD CDM	500V		3/0	
Manufacturability	per mfg. Site specification		Approved	
X-ray	top side only		5/0	
Notes: ** Tests require preconditioning sequence: JEDEC L-2/260C				

Reference Qual #14

信頼性試験結果				
信頼性試験期間	開始	—	終了	2010 年 4 月 8 日
信頼性試験 - 試料構成詳細				
Qual Device:	PGA308AIDGS	-	-	
Assembly Site:	ASE SHANGHAI	Package/Code/Pins:	VSSOP/DGS/10	
Mount Compound:	EY1000063	Mold Compound:	EN2000515	
Bond Wire:	1.0 mil Dia., Au	Leadframe (Finish, Base):	NiPdAuAg, Cu	
MSL:	JEDEC L-1/260C	-	-	
信頼性試験結果				
Reliability Test	Condition / Duration	Sample Size/ Fails		
		Lot #1	Lot #2	Lot #3
**Life Test	150C, 300 Hrs	77/0	77/0	77/0
**High Temp. Storage Bake	170C, 420 Hrs	77/0	77/0	77/0
**Biased HAST	130C/85%RH, 96 Hrs	77/0	77/0	77/0
**Autoclave	121C, 96 Hrs	77/0	77/0	77/0
**T/C	-65C/150C, 500 Cyc	77/0	77/0	77/0
Backgrind Characterization	-	Approved	-	-
Visual / Mechanical	-	Approved	Approved	Approved
Solderability	Steam age, 8 hours	22/0	22/0	22/0
Lead Fatigue	-	22/0	22/0	22/0
Lead Pull	To destruction	22/0	22/0	22/0
Lead Finish Adhesion	-	15/0	15/0	15/0
Physical Dimensions	per mechanical drawing	5/0	5/0	5/0
Flammability	Method A - UL94-0	5/0	5/0	5/0
Flammability	Method B - IEC 695-2-2	5/0	5/0	5/0
Flammability	Method C - UL 1694	5/0	5/0	5/0
Ball Bond Shear	Wires	80/0	80/0	80/0
Bond Pull	Wires	80/0	80/0	80/0
Die Shear	-	15/0	15/0	15/0
Manufacturability (Assembly)	per mfg. Site specification	Approved	Approved	Approved
**Thermal Shock	-65C/150C, 500 Cyc	77/0	77/0	77/0
Salt Atmosphere	24 Hrs	22/0	22/0	22/0
X-ray	top side only	5/0	5/0	5/0
Moisture Sensitivity	JEDEC L-1/260C	12/0	12/0	12/0
Note: ** Preconditioning sequence: JEDEC L-1/260C				

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信頼性試験結果				
信頼性試験期間	開始	—	終了	2010年4月8日
信頼性試験 - 試料構成詳細				
Qual Device:	THS4304DGK	-	-	
Assembly Site:	ASE (Shanghai)	Package/Code/Pins:	MSOP/DGK/8	
Mount Compound:	EY1000063	Mold Compound:	EN2000515	
Bond Wire:	1.0 mil Dia., Au	Leadframe (Finish, Base):	NiPdAuAg, Cu	
MSL:	JEDEC L-1/260C	-	-	
信頼性試験結果				
Reliability Test	Condition / Duration	Sample Size/ Fails		
		Lot #1	Lot #2	Lot #3
**Life Test	155C, 240 Hrs	77/0	77/0	77/0
**High Temp. Storage Bake	170C, 420 Hrs	77/0	77/0	77/0
**Biased HAST	130C/85%RH, 96 Hrs	77/0	77/0	77/0
**Autoclave	121C, 96 Hrs	77/0	77/0	77/0
**T/C	-65C/150C, 500 Cyc	82/0	82/0	82/0
Backgrind Characterization	-	Approved	-	-
Visual / Mechanical	-	Approved	Approved	Approved
Surface Mount Solderability	Steam age, 8 hours	22/0	22/0	22/0
Surface Mount Solderability	PB-Free solder	22/0	22/0	22/0
Lead Fatigue	-	22/0	22/0	22/0
Lead Pull	To destruction	22/0	22/0	22/0
Lead Finish Adhesion	-	15/0	15/0	15/0
Physical Dimensions	per mechanical drawing	20/0	-	-
Ball Bond Shear	Wires	80/0	80/0	80/0
Bond Pull	Wires	80/0	80/0	80/0
Die Shear	-	15/0	15/0	15/0
Manufacturability (Assembly)	per mfg. Site specification	Approved	Approved	Approved
**Thermal Shock	-65C/150C, 500 Cyc	77/0	77/0	77/0
Salt Atmosphere	24 Hrs	22/0	22/0	22/0
X-ray	top side only	5/0	5/0	5/0
Moisture Sensitivity	JEDEC L-1/260C	12/0	12/0	12/0
Note: ** Preconditioning sequence: JEDEC L-1/260C				

信頼性試験結果				
信頼性試験期間	開始	—	終了	2010年4月8日
信頼性試験 - 試料構成詳細				
Qual Device:	TLV2545IDGK	-	-	
Assembly Site:	ASE (Shanghai)	Package/Code/Pins:	MSSOP/DGK/8	
Mount Compound:	EY1000063	Mold Compound:	EN2000515	
Bond Wire:	1.0 mil Dia., Au	Leadframe (Finish, Base):	NiPdAuAg, Cu	
MSL:	JEDEC L-1/260C	-	-	
信頼性試験結果				
Reliability Test	Condition / Duration	Sample Size/ Fails		
		Lot #1	Lot #2	Lot #3
**High Temp. Storage Bake	170C, 420hrs Hrs	76/0	77/0	84/0
**Autoclave	121C, 96 Hrs	76/0	77/0	84/0
**T/C	-65C/150C, 500 Cyc	82/0	82/0	89/0
Backgrind Characterization	-	Approved	-	-
Visual / Mechanical	-	Approved	Approved	Approved
Surface Mount Solderability	Steam age, 8 hours	22/0	22/0	22/0
Surface Mount Solderability	PB-Free solder	22/0	22/0	22/0
Lead Fatigue	-	22/0	22/0	22/0
Lead Pull	To destruction	22/0	22/0	22/0
Lead Finish Adhesion	-	15/0	15/0	15/0
Ball Bond Shear	Wires	80/0	80/0	80/0
Bond Pull	Wires	80/0	80/0	80/0
Die Shear	-	15/0	15/0	15/0
Manufacturability (Assembly)	per mfg. Site specification	Approved	Approved	Approved
**Thermal Shock	-65C/150C, 500 Cyc	77/0	77/0	77/0
Salt Atmosphere	24 Hrs	22/0	22/0	22/0
X-ray	top side only	5/0	5/0	5/0
Moisture Sensitivity	JEDEC L-1/260C	12/0	12/0	12/0
Note: ** Preconditioning sequence: JEDEC L-1/260C				

信頼性試験結果				
信頼性試験期間	開始	—	終了	2010 年 4 月 8 日
信頼性試験 - 試料構成詳細				
Qual Device:	TPS62040DGQ	-	-	
Assembly Site:	ASE (Shanghai)	Package/Code/Pins:	MSOP/DGQ/10	
Mount Compound:	EY1000063	Mold Compound:	EN2000515	
Bond Wire:	1.0 mil Dia., Au	Leadframe (Finish, Base):	NiPdAuAg, Cu	
MSL:	JEDEC L-1/260C	-	-	
信頼性試験結果				
Reliability Test	Condition / Duration	Sample Size/ Fails		
		Lot #1	Lot #2	Lot #3
**High Temp. Storage Bake	170C, 420 Hrs	76/0	77/0	73/0
**Biased HAST	130C/85%RH, 96 Hrs	77/0	70/0	77/0
**Autoclave	121C, 96 Hrs	77/0	77/0	70/0
**T/C	-65C/150C, 500 Cyc	78/0	81/0	80/0
Visual / Mechanical	-	Approved	Approved	Approved
Surface Mount Solderability	Steam age, 8 hours	22/0	22/0	22/0
Surface Mount Solderability	PB-Free solder	22/0	22/0	22/0
Lead Fatigue	-	22/0	22/0	22/0
Lead Pull	To destruction	22/0	22/0	22/0
Lead Finish Adhesion	-	15/0	15/0	15/0
Physical Dimensions	per mechanical drawing	20/0	--	--
Flammability	Method A - UL94-0	5/0	5/0	5/0
Flammability	Method B - IEC 695-2-2	5/0	5/0	5/0
Flammability	Method C - UL 1694	5/0	5/0	5/0
Ball Bond Shear	Wires	80/0	76/0	76/0
Bond Pull	Wires	80/0	76/0	76/0
Die Shear	-	15/0	15/0	15/0
Manufacturability (Assembly)	per mfg. Site specification	Approved	Approved	Approved
**Thermal Shock	-65C/150C, 500 Cyc	77/0	77/0	77/0
Salt Atmosphere	24 Hrs	22/0	22/0	22/0
X-ray	top side only	5/0	5/0	--
Moisture Sensitivity	JEDEC L-1/260C	11/0	12/0	9/0
Note: ** Preconditioning sequence: JEDEC L-1/260C				

信頼性試験結果				
信頼性試験期間	開始	—	終了	2010 年 4 月 8 日
信頼性試験 - 試料構成詳細				
Qual Device:	VCA822IDGS	-	-	
Assembly Site:	ASE (Shanghai)	Package/Code/Pins:	MSOP/DGS/10	
Mount Compound:	EY1000063	Mold Compound:	EN2000515	
Bond Wire:	1.0 mil Dia., Au	Leadframe (Finish, Base):	NiPdAuAg, Cu	
MSL:	JEDEC L-2/260C	-	-	
信頼性試験結果				
Reliability Test	Condition / Duration		Sample Size/ Fails	
**High Temp. Storage Bake	170C, 420 Hrs		77/0	
**Autoclave	121C, 96 Hrs		77/0	
**T/C	-65C/150C, 500 Cyc		77/0	
Visual / Mechanical	-		Approved	
**Thermal Shock	-65C/150C, 500 Cyc		77/0	
Solderability	Steam age, 8 hours		22/0	
Ball Bond Shear	Wires		80/0	
Bond Pull	Wires		80/0	
Die Shear	-		15/0	
Manufacturability (Assembly)	per mfg. Site specification		Approved	
Salt Atmosphere	24 Hrs		22/0	
X-ray	top side only		5/0	
Note: ** Preconditioning sequence: JEDEC L-2/260C				